

# Michael G Pecht

## List of Publications by Citations

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The third column is the impact factor (IF) of the journal, and the fourth column is the number of citations of the article.

825  
papers

19,776  
citations

66  
h-index

115  
g-index

962  
ext. papers

25,339  
ext. citations

3.6  
avg. IF

7.59  
L-index

#	Paper	IF	Citations
825	Light emitting diodes reliability review. <i>Microelectronics Reliability</i> , <b>2012</b> , 52, 762-782	1.2	506
824	Prognostics of lithium-ion batteries based on Dempster-Shafer theory and the Bayesian Monte Carlo method. <i>Journal of Power Sources</i> , <b>2011</b> , 196, 10314-10321	8.9	434
823	State of charge estimation of lithium-ion batteries using the open-circuit voltage at various ambient temperatures. <i>Applied Energy</i> , <b>2014</b> , 113, 106-115	10.7	414
822	Long Short-Term Memory Recurrent Neural Network for Remaining Useful Life Prediction of Lithium-Ion Batteries. <i>IEEE Transactions on Vehicular Technology</i> , <b>2018</b> , 67, 5695-5705	6.8	366
821	. <i>IEEE Transactions on Reliability</i> , <b>2012</b> , 61, 50-67	4.6	320
820	Prognostics and health management of electronics. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2006</b> , 29, 222-229		288
819	Remaining useful life prediction of lithium-ion battery with unscented particle filter technique. <i>Microelectronics Reliability</i> , <b>2013</b> , 53, 805-810	1.2	287
818	<b>2008</b> ,		268
817	Prognostics for state of health estimation of lithium-ion batteries based on combination Gaussian process functional regression. <i>Microelectronics Reliability</i> , <b>2013</b> , 53, 832-839	1.2	266
816	Motor Bearing Fault Diagnosis Using Trace Ratio Linear Discriminant Analysis. <i>IEEE Transactions on Industrial Electronics</i> , <b>2014</b> , 61, 2441-2451	8.9	266
815	An ensemble model for predicting the remaining useful performance of lithium-ion batteries. <i>Microelectronics Reliability</i> , <b>2013</b> , 53, 811-820	1.2	254
814	Motor Bearing Fault Detection Using Spectral Kurtosis-Based Feature Extraction Coupled With K-Nearest Neighbor Distance Analysis. <i>IEEE Transactions on Industrial Electronics</i> , <b>2016</b> , 63, 1793-1803	8.9	248
813	Battery Management Systems in Electric and Hybrid Vehicles. <i>Energies</i> , <b>2011</b> , 4, 1840-1857	3.1	242
812	. <i>IEEE Transactions on Reliability</i> , <b>2013</b> , 62, 772-780	4.6	238
811	A review of fractional-order techniques applied to lithium-ion batteries, lead-acid batteries, and supercapacitors. <i>Journal of Power Sources</i> , <b>2018</b> , 390, 286-296	8.9	233
810	Prognostics of lithium-ion batteries based on relevance vectors and a conditional three-parameter capacity degradation model. <i>Journal of Power Sources</i> , <b>2013</b> , 239, 253-264	8.9	215
809	A prognostics and health management roadmap for information and electronics-rich systems. <i>Microelectronics Reliability</i> , <b>2010</b> , 50, 317-323	1.2	214

808	State of charge estimation for Li-ion batteries using neural network modeling and unscented Kalman filter-based error cancellation. <i>International Journal of Electrical Power and Energy Systems</i> , <b>2014</b> , 62, 783-791	5.1	208
807	State of charge estimation for electric vehicle batteries using unscented kalman filtering. <i>Microelectronics Reliability</i> , <b>2013</b> , 53, 840-847	1.2	206
806	Battery Lifetime Prognostics. <i>Joule</i> , <b>2020</b> , 4, 310-346	27.8	200
805	Effect of Temperature on the Aging rate of Li Ion Battery Operating above Room Temperature. <i>Scientific Reports</i> , <b>2015</b> , 5, 12967	4.9	199
804	A review of lead-free solders for electronics applications. <i>Microelectronics Reliability</i> , <b>2017</b> , 75, 77-95	1.2	195
803	Lessons Learned from the 787 Dreamliner Issue on Lithium-Ion Battery Reliability. <i>Energies</i> , <b>2013</b> , 6, 4683-4695	3.4	189
802	Influence of different open circuit voltage tests on state of charge online estimation for lithium-ion batteries. <i>Applied Energy</i> , <b>2016</b> , 183, 513-525	10.7	182
801	Deep Residual Shrinkage Networks for Fault Diagnosis. <i>IEEE Transactions on Industrial Informatics</i> , <b>2020</b> , 16, 4681-4690	11.9	181
800	Deep Residual Networks With Dynamically Weighted Wavelet Coefficients for Fault Diagnosis of Planetary Gearboxes. <i>IEEE Transactions on Industrial Electronics</i> , <b>2018</b> , 65, 4290-4300	8.9	180
799	Development of an optimized condition-based maintenance system by data fusion and reliability-centered maintenance. <i>Reliability Engineering and System Safety</i> , <b>2010</b> , 95, 786-796	6.3	155
798	A failure modes, mechanisms, and effects analysis (FMMEA) of lithium-ion batteries. <i>Journal of Power Sources</i> , <b>2015</b> , 297, 113-120	8.9	150
797	. <i>IEEE Transactions on Reliability</i> , <b>2009</b> , 58, 271-276	4.6	143
796	Sensor systems for prognostics and health management. <i>Sensors</i> , <b>2010</b> , 10, 5774-97	3.8	142
795	. <i>IEEE Transactions on Industrial Electronics</i> , <b>2018</b> , 65, 1526-1538	8.9	142
794	Lithium-Ion Battery Health Prognosis Based on a Real Battery Management System Used in Electric Vehicles. <i>IEEE Transactions on Vehicular Technology</i> , <b>2019</b> , 68, 4110-4121	6.8	141
793	Application of a state space modeling technique to system prognostics based on a health index for condition-based maintenance. <i>Mechanical Systems and Signal Processing</i> , <b>2012</b> , 28, 585-596	7.8	133
792	Lithium-ion battery remaining useful life estimation based on fusion nonlinear degradation AR model and RPF algorithm. <i>Neural Computing and Applications</i> , <b>2014</b> , 25, 557-572	4.8	124
791	IoT-Based Prognostics and Systems Health Management for Industrial Applications. <i>IEEE Access</i> , <b>2016</b> , 4, 3659-3670	3.5	123

790	Diagnostics and Prognostics Method for Analog Electronic Circuits. <i>IEEE Transactions on Industrial Electronics</i> , <b>2013</b> , 60, 5277-5291	8.9	122
789	. <i>IEEE Transactions on Reliability</i> , <b>1991</b> , 40, 531-536	4.6	122
788	No-fault-found and intermittent failures in electronic products. <i>Microelectronics Reliability</i> , <b>2008</b> , 48, 663-674	1.2	120
787	Lifetime Estimation of High-Power White LED Using Degradation-Data-Driven Method. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2012</b> , 12, 470-477	1.6	118
786	Physics-of-failure-based prognostics for electronic products. <i>Transactions of the Institute of Measurement and Control</i> , <b>2009</b> , 31, 309-322	1.8	118
785	. <i>IEEE Transactions on Reliability</i> , <b>2012</b> , 61, 323-335	4.6	116
784	Vibration model of rolling element bearings in a rotor-bearing system for fault diagnosis. <i>Journal of Sound and Vibration</i> , <b>2013</b> , 332, 2081-2097	3.9	109
783	Li-Ion Battery Fire Hazards and Safety Strategies. <i>Energies</i> , <b>2018</b> , 11, 2191	3.1	106
782	MEMS Reliability Review. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2012</b> , 12, 482-493	1.6	104
781	Lithium-Ion Battery Remaining Useful Life Prediction With Box-Cox Transformation and Monte Carlo Simulation. <i>IEEE Transactions on Industrial Electronics</i> , <b>2019</b> , 66, 1585-1597	8.9	103
780	Battery warm-up methodologies at subzero temperatures for automotive applications: Recent advances and perspectives. <i>Progress in Energy and Combustion Science</i> , <b>2020</b> , 77, 100806	33.6	98
779	Hygroscopic swelling and sorption characteristics of epoxy molding compounds used in electronic packaging. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2003</b> , 26, 206-214		90
778	<b>2006</b> ,		87
777	A life consumption monitoring methodology for electronic systems. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2003</b> , 26, 625-634		86
776	Predicting long-term lumen maintenance life of LED light sources using a particle filter-based prognostic approach. <i>Expert Systems With Applications</i> , <b>2015</b> , 42, 2411-2420	7.8	85
775	A prognostic approach for non-punch through and field stop IGBTs. <i>Microelectronics Reliability</i> , <b>2012</b> , 52, 482-488	1.2	84
774	Characterization of hygroscopic swelling behavior of mold compounds and plastic packages. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2004</b> , 27, 499-506		84
773	Multiple Wavelet Coefficients Fusion in Deep Residual Networks for Fault Diagnosis. <i>IEEE Transactions on Industrial Electronics</i> , <b>2019</b> , 66, 4696-4706	8.9	84

772	. <i>Proceedings of the IEEE</i> , <b>1994</b> , 82, 992-1004	14.3	81
771	Electronic part life cycle concepts and obsolescence forecasting. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2000</b> , 23, 707-717		78
770	Prognostics implementation of electronics under vibration loading. <i>Microelectronics Reliability</i> , <b>2007</b> , 47, 1849-1856	1.2	77
769	A generic model-free approach for lithium-ion battery health management. <i>Applied Energy</i> , <b>2014</b> , 135, 247-260	10.7	76
768	Cycle life testing and modeling of graphite/LiCoO <sub>2</sub> cells under different state of charge ranges. <i>Journal of Power Sources</i> , <b>2016</b> , 327, 394-400	8.9	76
767	A Hybrid Feature Selection Scheme for Reducing Diagnostic Performance Deterioration Caused by Outliers in Data-Driven Diagnostics. <i>IEEE Transactions on Industrial Electronics</i> , <b>2016</b> , 63, 3299-3310	8.9	75
766	Particle Learning Framework for Estimating the Remaining Useful Life of Lithium-Ion Batteries. <i>IEEE Transactions on Instrumentation and Measurement</i> , <b>2017</b> , 66, 280-293	5.2	75
765	Estimation of remaining useful life of ball bearings using data driven methodologies <b>2012</b> ,		75
764	<b>2014</b> ,		74
763	. <i>IEEE Transactions on Reliability</i> , <b>2010</b> , 59, 277-286	4.6	73
762	. <i>IEEE Transactions on Reliability</i> , <b>1992</b> , 41, 72-75	4.6	72
761	Physics-of-Failure-Based Prognostics and Health Management for High-Power White Light-Emitting Diode Lighting. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2011</b> , 11, 407-416	1.6	71
760	A Bayesian approach for Li-Ion battery capacity fade modeling and cycles to failure prognostics. <i>Journal of Power Sources</i> , <b>2015</b> , 281, 173-184	8.9	70
759	. <i>IEEE Transactions on Instrumentation and Measurement</i> , <b>2012</b> , 61, 2222-2229	5.2	66
758	. <i>IEEE Transactions on Reliability</i> , <b>2013</b> , 62, 136-145	4.6	66
757	A multi-component and multi-failure mode inspection model based on the delay time concept. <i>Reliability Engineering and System Safety</i> , <b>2010</b> , 95, 912-920	6.3	65
756	An Online SOC and SOH Estimation Model for Lithium-Ion Batteries. <i>Energies</i> , <b>2017</b> , 10, 512	3.1	63
755	The impact of lead-free legislation exemptions on the electronics industry. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2004</b> , 27, 221-232		62

754	Interacting multiple model particle filter for prognostics of lithium-ion batteries. <i>Microelectronics Reliability</i> , <b>2017</b> , 70, 59-69	1.2	61
753	. <i>IEEE Transactions on Instrumentation and Measurement</i> , <b>2010</b> , 59, 2055-2064	5.2	61
752	Prognostics uncertainty reduction by fusing on-line monitoring data based on a state-space-based degradation model. <i>Mechanical Systems and Signal Processing</i> , <b>2014</b> , 45, 396-407	7.8	57
751	Advanced battery management strategies for a sustainable energy future: Multilayer design concepts and research trends. <i>Renewable and Sustainable Energy Reviews</i> , <b>2021</b> , 138, 110480	16.2	57
750	Enhanced Reliability Modeling of RAID Storage Systems <b>2007</b> ,		56
749	The trouble not identified phenomenon in automotive electronics. <i>Microelectronics Reliability</i> , <b>2002</b> , 42, 641-651	1.2	56
748	In-situ sensors for product reliability monitoring <b>2002</b> ,		54
747	A Review of Prognostic Techniques for High-Power White LEDs. <i>IEEE Transactions on Power Electronics</i> , <b>2017</b> , 32, 6338-6362	7.2	53
746	Validation and verification of a hybrid method for remaining useful life prediction of lithium-ion batteries. <i>Journal of Cleaner Production</i> , <b>2019</b> , 212, 240-249	10.3	53
745	High lead solder (over 85 %) solder in the electronics industry: RoHS exemptions and alternatives. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2015</b> , 26, 4021-4030	2.1	49
744	Copper Wire Bonding Concerns and Best Practices. <i>Journal of Electronic Materials</i> , <b>2013</b> , 42, 2415-2434	1.9	49
743	Statistical analysis of tin whisker growth. <i>Microelectronics Reliability</i> , <b>2006</b> , 46, 846-849	1.2	49
742	. <i>IEEE Transactions on Components, Hybrids and Manufacturing Technology</i> , <b>1992</b> , 15, 1160-1164		49
741	Aging characteristics-based health diagnosis and remaining useful life prognostics for lithium-ion batteries. <i>ETransportation</i> , <b>2019</b> , 1, 100004	12.7	48
740	A Highly Accurate Method for Assessing Reliability of Redundant Arrays of Inexpensive Disks (RAID). <i>IEEE Transactions on Computers</i> , <b>2009</b> , 58, 289-299	2.5	48
739	Using cross-validation for model parameter selection of sequential probability ratio test. <i>Expert Systems With Applications</i> , <b>2012</b> , 39, 8467-8473	7.8	47
738	State of charge estimation based on a simplified electrochemical model for a single LiCoO <sub>2</sub> battery and battery pack. <i>Energy</i> , <b>2017</b> , 133, 572-583	7.9	46
737	Temperature dependent power capability estimation of lithium-ion batteries for hybrid electric vehicles. <i>Energy</i> , <b>2016</b> , 113, 64-75	7.9	46

736	. <i>IEEE Transactions on Industrial Electronics</i> , <b>2017</b> , 64, 605-614	8.9	46
735	Prognostics-based risk mitigation for telecom equipment under free air cooling conditions. <i>Applied Energy</i> , <b>2012</b> , 99, 423-429	10.7	46
734	. <i>IEEE Transactions on Industrial Electronics</i> , <b>2011</b> , 58, 3077-3089	8.9	46
733	A Wireless Sensor System for Prognostics and Health Management. <i>IEEE Sensors Journal</i> , <b>2010</b> , 10, 856-862	4.6	46
732	The impact of electrical current, mechanical bending, and thermal annealing on tin whisker growth. <i>Microelectronics Reliability</i> , <b>2007</b> , 47, 88-92	1.2	46
731	In situ temperature measurement of a notebook computer - a case study in health and usage monitoring of electronics. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2004</b> , 4, 658-663	1.6	46
730	Warpage Analysis of Flip-Chip PBGA Packages Subject to Thermal Loading. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2009</b> , 9, 419-424	1.6	45
729	A new member of the C-type lectin family is a modulator of the mast cell secretory response. <i>International Archives of Allergy and Immunology</i> , <b>1995</b> , 107, 82-6	3.7	45
728	Machine learning pipeline for battery state-of-health estimation. <i>Nature Machine Intelligence</i> , <b>2021</b> , 3, 447-456	22.5	45
727	In Situ Stress Measurement Techniques on Li-ion Battery Electrodes: A Review. <i>Energies</i> , <b>2017</b> , 10, 591	3.1	44
726	. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2011</b> , 11, 328-338	1.6	44
725	Intermetallics Characterization of Lead-Free Solder Joints under Isothermal Aging. <i>Journal of Electronic Materials</i> , <b>2008</b> , 37, 1130-1138	1.9	44
724	Electronic device encapsulation using red phosphorus flame retardants. <i>Microelectronics Reliability</i> , <b>2006</b> , 46, 53-62	1.2	44
723	Recognition of protein substrates by the prolyl isomerase trigger factor is independent of proline residues. <i>Journal of Molecular Biology</i> , <b>1998</b> , 277, 723-32	6.5	44
722	Deep Residual Networks With Adaptively Parametric Rectifier Linear Units for Fault Diagnosis. <i>IEEE Transactions on Industrial Electronics</i> , <b>2021</b> , 68, 2587-2597	8.9	44
721	Health assessment of cooling fan bearings using wavelet-based filtering. <i>Sensors</i> , <b>2012</b> , 13, 274-91	3.8	43
720	The reliability physics approach to failure prediction modelling. <i>Quality and Reliability Engineering International</i> , <b>1990</b> , 6, 267-273	2.6	43
719	Accelerated degradation model for C-rate loading of lithium-ion batteries. <i>International Journal of Electrical Power and Energy Systems</i> , <b>2019</b> , 107, 438-445	5.1	43

718	Model-based and data-driven prognosis of automotive and electronic systems <b>2009</b> ,		42
717	A Rotating Machinery Fault Diagnosis Method Based on Feature Learning of Thermal Images. <i>IEEE Access</i> , <b>2019</b> , 7, 12348-12359	3.5	41
716	Accelerated cycle life testing and capacity degradation modeling of LiCoO <sub>2</sub> -graphite cells. <i>Journal of Power Sources</i> , <b>2019</b> , 435, 226830	8.9	41
715	Health monitoring of electronic products based on Mahalanobis distance and Weibull decision metrics. <i>Microelectronics Reliability</i> , <b>2011</b> , 51, 279-284	1.2	41
714	Parameter selection for health monitoring of electronic products. <i>Microelectronics Reliability</i> , <b>2010</b> , 50, 161-168	1.2	41
713	. <i>IEEE Transactions on Components, Hybrids and Manufacturing Technology</i> , <b>1990</b> , 13, 383-389		41
712	<b>2009</b> ,		40
711	Ensemble-approaches for clustering health status of oil sand pumps. <i>Expert Systems With Applications</i> , <b>2012</b> , 39, 4847-4859	7.8	39
710	Identification of failure precursor parameters for Insulated Gate Bipolar Transistors (IGBTs) <b>2008</b> ,		39
709	Reliability of Printed Circuit Boards Processed Using No-Clean Flux Technology in TemperatureHumidityBias Conditions. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2008</b> , 8, 426-434	1.6	39
708	A Prognostic Model for Stochastic Degrading Systems With State Recovery: Application to Li-Ion Batteries. <i>IEEE Transactions on Reliability</i> , <b>2017</b> , 66, 1293-1308	4.6	38
707	Tin whisker analysis of Toyota's electronic throttle controls. <i>Circuit World</i> , <b>2011</b> , 37, 4-9	0.7	38
706	Point-of-care biosensor system. <i>Frontiers in Bioscience - Scholar</i> , <b>2013</b> , 5, 39-71	2.4	38
705	Surface Insulation Resistance of Conformally Coated Printed Circuit Boards Processed With No-Clean Flux. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2006</b> , 29, 217-223		37
704	Prognostics of lumen maintenance for High power white light emitting diodes using a nonlinear filter-based approach. <i>Reliability Engineering and System Safety</i> , <b>2014</b> , 123, 63-72	6.3	36
703	Prognostics of Failures in Embedded Planar Capacitors using Model-Based and Data-Driven Approaches. <i>Journal of Intelligent Material Systems and Structures</i> , <b>2011</b> , 22, 1293-1304	2.3	36
702	Hybrid electrochemical energy storage systems: An overview for smart grid and electrified vehicle applications. <i>Renewable and Sustainable Energy Reviews</i> , <b>2021</b> , 139, 110581	16.2	36
701	Analysis of Manufacturing-Induced Defects and Structural Deformations in Lithium-Ion Batteries Using Computed Tomography. <i>Energies</i> , <b>2018</b> , 11, 925	3.1	36

700	Health monitoring of cooling fan bearings based on wavelet filter. <i>Mechanical Systems and Signal Processing</i> , <b>2015</b> , 64-65, 149-161	7.8	35
699	. <i>IEEE Transactions on Industrial Informatics</i> , <b>2014</b> , 10, 1852-1863	11.9	35
698	Early Detection of Interconnect Degradation by Continuous Monitoring of RF Impedance. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2009</b> , 9, 296-304	1.6	35
697	A probabilistic description scheme for rotating machinery health evaluation. <i>Journal of Mechanical Science and Technology</i> , <b>2010</b> , 24, 2421-2430	1.6	35
696	Modeling of Combined Temperature Cycling and Vibration Loading on PBGA Solder Joints Using an Incremental Damage Superposition Approach. <i>IEEE Transactions on Advanced Packaging</i> , <b>2008</b> , 31, 463-472		35
695	Reliability risk mitigation of free air cooling through prognostics and health management. <i>Applied Energy</i> , <b>2013</b> , 111, 104-112	10.7	34
694	Electrostatic Monitoring of Gas Path Debris for Aero-engines. <i>IEEE Transactions on Reliability</i> , <b>2011</b> , 60, 33-40	4.6	34
693	A Rapid Life-Prediction Approach for PBGA Solder Joints Under Combined Thermal Cycling and Vibration Loading Conditions. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2009</b> , 32, 283-292		34
692	An experimental study of popcorning in plastic encapsulated microcircuits. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>1996</b> , 19, 194-201		34
691	. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2014</b> , 14, 564-573	1.6	33
690	Rare-Earth Elements in Lighting and Optical Applications and Their Recycling. <i>Jom</i> , <b>2013</b> , 65, 1276-1282	2.1	33
689	An Assessment of Immersion Silver Surface Finish for Lead-Free Electronics. <i>Journal of Electronic Materials</i> , <b>2009</b> , 38, 815-827	1.9	33
688	Chinese science and technology Structure and infrastructure. <i>Technological Forecasting and Social Change</i> , <b>2007</b> , 74, 1539-1573	9.5	33
687	Pressure-induced tin whisker formation. <i>Microelectronics Reliability</i> , <b>2008</b> , 48, 1033-1039	1.2	33
686	Environment and Usage Monitoring of Electronic Products for Health Assessment and Product Design. <i>Quality Technology and Quantitative Management</i> , <b>2007</b> , 4, 235-250	1.9	33
685	Preliminary Study on Integration of Fiber Optic Bragg Grating Sensors in Li-Ion Batteries and In Situ Strain and Temperature Monitoring of Battery Cells. <i>Energies</i> , <b>2017</b> , 10, 838	3.1	32
684	Commercial impact of silicon carbide. <i>IEEE Industrial Electronics Magazine</i> , <b>2008</b> , 2, 19-31	6.2	32
683	Critical Review of the Engelmaier Model for Solder Joint Creep Fatigue Reliability. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2009</b> , 32, 693-700		31

682	Failure mechanisms based prognostics <b>2008</b> ,		31
681	Field failure due to creep corrosion on components with palladium pre-plated leadframes. <i>Microelectronics Reliability</i> , <b>2003</b> , 43, 775-783	1.2	31
680	. <i>IEEE Transactions on Advanced Packaging</i> , <b>1994</b> , 17, 269-276		31
679	<b>2012</b> ,		31
678	. <i>IEEE Access</i> , <b>2018</b> , 6, 18088-18107	3.5	30
677	Identification of Failure Mechanisms to Enhance Prognostic Outcomes. <i>Journal of Failure Analysis and Prevention</i> , <b>2012</b> , 12, 66-73	0.9	30
676	. <i>IEEE Transactions on Reliability</i> , <b>2012</b> , 61, 872-883	4.6	30
675	Economics of rare earth elements in ceramic capacitors. <i>Ceramics International</i> , <b>2012</b> , 38, 6091-6098	5.1	30
674	Identification of multiple characteristic components with high accuracy and resolution using the zoom interpolated discrete Fourier transform. <i>Measurement Science and Technology</i> , <b>2011</b> , 22, 055701	2	30
673	Prognostics and health management using physics-of-failure <b>2008</b> ,		30
672	Impact of environmental regulations on green electronics manufacture. <i>Microelectronics International</i> , <b>2006</b> , 23, 45-50	0.8	30
671	Ion transport in encapsulants used in microcircuit packaging. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2003</b> , 26, 199-205		30
670	A Probabilistic Approach for Predicting Thermal Fatigue Life of Wire Bonding in Microelectronics. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , <b>1991</b> , 113, 275-285	2	30
669	An adaptive state of charge estimation approach for lithium-ion series-connected battery system. <i>Journal of Power Sources</i> , <b>2018</b> , 392, 48-59	8.9	29
668	Quantitative Analysis of Lithium-Ion Battery Capacity Prediction via Adaptive Bathtub-Shaped Function. <i>Energies</i> , <b>2013</b> , 6, 3082-3096	3.1	29
667	Disassembly methodology for conducting failure analysis on lithium-ion batteries. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2011</b> , 22, 1616-1630	2.1	29
666	In-situ measurements of surface mount IC package deformations during reflow soldering. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology Part C Manufacturing</i> , <b>1997</b> , 20, 207-212		29
665	Electromigration and thermomigration behavior of flip chip solder joints in high current density packages. <i>Journal of Materials Research</i> , <b>2008</b> , 23, 2333-2339	2.5	29

664	Are you ready for lead-free electronics?. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2005</b> , 28, 884-894		29
663	Moisture ingress into organic laminates. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>1999</b> , 22, 104-110		29
662	Remaining useful life prediction for lithium-ion batteries based on an integrated health indicator. <i>Microelectronics Reliability</i> , <b>2018</b> , 88-90, 1189-1194	1.2	29
661	Effect of Temperature and Relative Humidity on the Impedance Degradation of Dust-Contaminated Electronics. <i>Journal of the Electrochemical Society</i> , <b>2013</b> , 160, C97-C105	3.9	28
660	Prognostics implementation methods for electronics <b>2007</b> ,		28
659	Characterization of plastic encapsulant materials as a baseline for quality assessment and reliability testing. <i>Microelectronics Reliability</i> , <b>2002</b> , 42, 1163-1170	1.2	28
658	. <i>IEEE Systems Journal</i> , <b>2018</b> , 12, 2509-2523	4.3	27
657	The Effect of Inverter Failures on the Return on Investment of Solar Photovoltaic Systems. <i>IEEE Access</i> , <b>2017</b> , 5, 21336-21343	3.5	27
656	Prognostics of ceramic capacitor temperature-humidity-bias reliability using Mahalanobis distance analysis. <i>Circuit World</i> , <b>2007</b> , 33, 21-28	0.7	27
655	Lead-free soldering in the Japanese electronics industry. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2003</b> , 26, 616-624		27
654	Part manufacturer assessment process. <i>Quality and Reliability Engineering International</i> , <b>1999</b> , 15, 457-468	6.6	27
653	Remaining useful life estimation of lithium-ion cells based on k-nearest neighbor regression with differential evolution optimization. <i>Journal of Cleaner Production</i> , <b>2020</b> , 249, 119409	10.3	27
652	Current Noise Cancellation for Bearing Fault Diagnosis Using Time Shifting. <i>IEEE Transactions on Industrial Electronics</i> , <b>2017</b> , 64, 8138-8147	8.9	26
651	Exploding E-Cigarettes: A Battery Safety Issue. <i>IEEE Access</i> , <b>2018</b> , 6, 21442-21466	3.5	26
650	A health indicator method for degradation detection of electronic products. <i>Microelectronics Reliability</i> , <b>2012</b> , 52, 439-445	1.2	26
649	IEEE 1413: A Standard for Reliability Predictions. <i>IEEE Transactions on Reliability</i> , <b>2012</b> , 61, 125-129	4.6	26
648	Evaluation of Effectiveness of Conformal Coatings as Tin Whisker Mitigation. <i>Journal of Electronic Materials</i> , <b>2012</b> , 41, 2508-2518	1.9	26
647	. <i>IEEE Transactions on Computer-Aided Design of Integrated Circuits and Systems</i> , <b>1990</b> , 9, 734-744	2.5	26

646	A Physics-Based Electrochemical Model for Lithium-Ion Battery State-of-Charge Estimation Solved by an Optimised Projection-Based Method and Moving-Window Filtering. <i>Energies</i> , <b>2018</b> , 11, 2120	3.1	26
645	Copper Wire Bonding <b>2014</b> ,		26
644	On physical-layer concepts and metrics in secure signal transmission. <i>Physical Communication</i> , <b>2017</b> , 25, 14-25	2.2	25
643	Effects of Temperature Cycling and Elevated Temperature/Humidity on the Thermal Performance of Thermal Interface Materials. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2009</b> , 9, 379-391	1.6	25
642	Analysis of Solder Joint Failure Criteria and Measurement Techniques in the Qualification of Electronic Products. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2008</b> , 31, 469-477		25
641	Flex Cracking of Multilayer Ceramic Capacitors Assembled With Pb-Free and Tin-Lead Solders. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2008</b> , 8, 182-192	1.6	25
640	. <i>IEEE Transactions on Aerospace and Electronic Systems</i> , <b>2001</b> , 37, 266-271	3.7	25
639	Comparisons of the structure and infrastructure of Chinese and Indian Science and Technology. <i>Technological Forecasting and Social Change</i> , <b>2007</b> , 74, 1609-1630	9.5	24
638	Reduction of skin stretch induced motion artifacts in electrocardiogram monitoring using adaptive filtering. <i>Annual International Conference of the IEEE Engineering in Medicine and Biology Society</i> , <b>2006</b> , 2006, 6045-8		24
637	Conductive filament formation failure in a printed circuit board. <i>Circuit World</i> , <b>1999</b> , 25, 6-8	0.7	24
636	. <i>IEEE Transactions on Industrial Electronics</i> , <b>2017</b> , 64, 5667-5677	8.9	23
635	Evaluation of pure tin plated copper alloy substrates for tin whiskers. <i>Circuit World</i> , <b>2009</b> , 35, 3-8	0.7	23
634	Effect of the methionine ligand on the reorganization energy of the type-1 copper site of nitrite reductase. <i>Journal of the American Chemical Society</i> , <b>2007</b> , 129, 519-25	16.4	23
633	Assessment of China's and India's science and technology literature [Introduction, background, and approach. <i>Technological Forecasting and Social Change</i> , <b>2007</b> , 74, 1519-1538	9.5	23
632	Failure analysis and redesign of a helix upper dispenser. <i>Engineering Failure Analysis</i> , <b>2008</b> , 15, 642-653	3.2	23
631	Product Reliability, Maintainability, and Supportability Handbook		23
630	Remaining-Life Prediction of Solder Joints Using RF Impedance Analysis and Gaussian Process Regression. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2015</b> , 5, 1602-1609	1.7	22
629	Detection of Generalized-Roughness and Single-Point Bearing Faults Using Linear Prediction-Based Current Noise Cancellation. <i>IEEE Transactions on Industrial Electronics</i> , <b>2018</b> , 65, 9728-9738	8.9	22

628	In-Situ Observations of Lithium Dendrite Growth. <i>IEEE Access</i> , <b>2018</b> , 6, 8387-8393	3.5	22
627	<b>2012</b> ,		22
626	Embedded Capacitors in Printed Wiring Board: A Technological Review. <i>Journal of Electronic Materials</i> , <b>2012</b> , 41, 2286-2303	1.9	22
625	Temperature and voltage aging effects on electrical conduction mechanism in epoxy-BaTiO <sub>3</sub> composite dielectric used in embedded capacitors. <i>Microelectronics Reliability</i> , <b>2011</b> , 51, 946-952	1.2	22
624	Failure analysis and redesign of the evaporator tubing in a Kimchi refrigerator. <i>Engineering Failure Analysis</i> , <b>2010</b> , 17, 369-379	3.2	22
623	Establishing a Relationship Between Warranty and Reliability. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2006</b> , 29, 184-190		22
622	Strain range fatigue life assessment of lead-free solder interconnects subject to temperature cycle loading. <i>Soldering and Surface Mount Technology</i> , <b>2007</b> , 19, 12-17	1.4	22
621	Moisture induced degradation of multilayer ceramic capacitors. <i>Microelectronics Reliability</i> , <b>2006</b> , 46, 400-408	1.2	22
620	. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2002</b> , 25, 132-139		22
619	How failure prediction methodology affects electronic equipment design. <i>Quality and Reliability Engineering International</i> , <b>1990</b> , 6, 243-249	2.6	22
618	Detection and Reliability Risks of Counterfeit Electrolytic Capacitors. <i>IEEE Transactions on Reliability</i> , <b>2014</b> , 63, 468-479	4.6	21
617	Challenges in the Qualification of Electronic Components and Systems. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2013</b> , 13, 26-35	1.6	21
616	Review of Capabilities of the ENEPIG Surface Finish. <i>Journal of Electronic Materials</i> , <b>2014</b> , 43, 3885-3897	1.9	21
615	Using maintenance options to maximize the benefits of prognostics for wind farms. <i>Wind Energy</i> , <b>2014</b> , 17, 775-791	3.4	21
614	Evaluation of Electrochemical Migration on Printed Circuit Boards with Lead-Free and Tin-Lead Solder. <i>Journal of Electronic Materials</i> , <b>2011</b> , 40, 1921-1936	1.9	21
613	Reliability design of a reciprocating compressor suction reed valve in a common refrigerator subjected to repetitive pressure loads. <i>Engineering Failure Analysis</i> , <b>2010</b> , 17, 979-991	3.2	21
612	Design-of-experiment methods for computational parametric studies in electronic packaging. <i>Finite Elements in Analysis and Design</i> , <b>1998</b> , 30, 125-146	2.2	21
611	Environmental aging and deadhesion of siloxane-polyimide-epoxy adhesive. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2003</b> , 26, 524-531		21

610	Questions concerning the migration to lead-free solder. <i>Circuit World</i> , <b>2004</b> , 30, 34-40	0.7	21
609	Fault Diagnosis Using Adaptive Multifractal Detrended Fluctuation Analysis. <i>IEEE Transactions on Industrial Electronics</i> , <b>2020</b> , 67, 2272-2282	8.9	21
608	Anomaly detection for IGBTs using Mahalanobis distance. <i>Microelectronics Reliability</i> , <b>2015</b> , 55, 1054-1059		20
607	Ultrasonic Health Monitoring of Lithium-Ion Batteries. <i>Electronics (Switzerland)</i> , <b>2019</b> , 8, 751	2.6	20
606	An Enhanced Prognostic Model for Intermittent Failures in Digital Electronics <b>2007</b> ,		20
605	<b>2004</b> ,		20
604	. <i>IEEE Transactions on Reliability</i> , <b>1989</b> , 38, 199-205	4.6	20
603	Mitigation strategies for Li-ion battery thermal runaway: A review. <i>Renewable and Sustainable Energy Reviews</i> , <b>2021</b> , 150, 111437	16.2	20
602	Failure mechanisms of ball bearings under lightly loaded, non-accelerated usage conditions. <i>Tribology International</i> , <b>2015</b> , 81, 291-299	4.9	19
601	Joint PHY/MAC Layer Security Design Using ARQ With MRC and Null-Space Independent PAPR-Aware Artificial Noise in SISO Systems. <i>IEEE Transactions on Wireless Communications</i> , <b>2018</b> , 17, 6190-6204	9.6	19
600	Algorithm to Determine the Knee Point on Capacity Fade Curves of Lithium-Ion Cells. <i>Energies</i> , <b>2019</b> , 12, 2910	3.1	19
599	Carbon footprinting of electronic products. <i>Applied Energy</i> , <b>2014</b> , 136, 636-648	10.7	19
598	Color Shift Failure Prediction for Phosphor-Converted White LEDs by Modeling Features of Spectral Power Distribution with a Nonlinear Filter Approach. <i>Materials</i> , <b>2017</b> , 10,	3.5	19
597	A return on investment analysis of applying health monitoring to LED lighting systems. <i>Microelectronics Reliability</i> , <b>2015</b> , 55, 527-537	1.2	19
596	Design of a hinge kit system in a Kimchi refrigerator receiving repetitive stresses. <i>Engineering Failure Analysis</i> , <b>2009</b> , 16, 1655-1665	3.2	19
595	Microstructure and Intermetallic Formation in SnAgCu BGA Components Attached With SnPb Solder Under Isothermal Aging. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2008</b> , 8, 160-167	1.6	19
594	The Effect of Annealing on Tin Whisker Growth. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2006</b> , 29, 252-258		19
593	Tin whisker risk assessment. <i>Circuit World</i> , <b>2006</b> , 32, 25-29	0.7	19

592	Characterization of functional relationship between temperature and microelectronic reliability. <i>Microelectronics Reliability</i> , <b>1995</b> , 35, 377-402	1.2	19
591	The influence of temperature on integrated circuit failure mechanisms. <i>Quality and Reliability Engineering International</i> , <b>1992</b> , 8, 167-176	2.6	19
590	Multiple wavelet regularized deep residual networks for fault diagnosis. <i>Measurement: Journal of the International Measurement Confederation</i> , <b>2020</b> , 152, 107331	4.6	19
589	A Bayesian nonlinear random effects model for identification of defective batteries from lot samples. <i>Journal of Power Sources</i> , <b>2017</b> , 342, 342-350	8.9	18
588	Predicting Damage and Life Expectancy of Subsea Power Cables in Offshore Renewable Energy Applications. <i>IEEE Access</i> , <b>2019</b> , 7, 54658-54669	3.5	18
587	Thermal reliability prediction and analysis for high-density electronic systems based on the Markov process. <i>Microelectronics Reliability</i> , <b>2016</b> , 56, 182-188	1.2	18
586	Intermittent Failures in Hardware and Software. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , <b>2014</b> , 136,	2	18
585	Rolling element bearing fault feature extraction using EMD-based independent component analysis <b>2011</b> ,		18
584	Prognostics and Health Management of Electronics <b>2008</b> ,		18
583	Plastic Ball Grid Array Solder Joint Reliability for Avionics Applications. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2007</b> , 30, 242-247		18
582	A risk-informed methodology for parts selection and management. <i>Quality and Reliability Engineering International</i> , <b>1999</b> , 15, 261-271	2.6	18
581	. <i>IEEE Transactions on Advanced Packaging</i> , <b>1994</b> , 17, 632-639		18
580	A reliability assessment guide for the transition planning to lead-free electronics for companies whose products are RoHS exempted or excluded. <i>Microelectronics Reliability</i> , <b>2016</b> , 62, 113-123	1.2	18
579	RoHS compliance in safety and reliability critical electronics. <i>Microelectronics Reliability</i> , <b>2016</b> , 65, 1-7	1.2	18
578	State of charge-dependent aging mechanisms in graphite/Li(NiCoAl)O <sub>2</sub> cells: Capacity loss modeling and remaining useful life prediction. <i>Applied Energy</i> , <b>2019</b> , 255, 113818	10.7	17
577	Aging modes analysis and physical parameter identification based on a simplified electrochemical model for lithium-ion batteries. <i>Journal of Energy Storage</i> , <b>2020</b> , 31, 101538	7.8	17
576	Malfunctions of Medical Devices Due to Electrostatic Occurrences Big Data Analysis of 10 Years of the FDA Reports. <i>IEEE Access</i> , <b>2018</b> , 6, 5805-5811	3.5	17
575	A cloud model-based method for the analysis of accelerated life test data. <i>Microelectronics Reliability</i> , <b>2015</b> , 55, 123-128	1.2	17

574	Screening for counterfeit electronic parts. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2011</b> , 22, 1511-1522	2.1	17
573	Health monitoring of hard disk drive based on Mahalanobis distance <b>2011</b> ,		17
572	Reliability design and case study of a refrigerator compressor subjected to repetitive loads. <i>International Journal of Refrigeration</i> , <b>2009</b> , 32, 478-486	3.8	17
571	Improving the reliability of a water dispenser lever in a refrigerator subjected to repetitive stresses. <i>Engineering Failure Analysis</i> , <b>2009</b> , 16, 1597-1606	3.2	17
570	A Prognostics and Health Management Roadmap for Information and Electronics-Rich Systems. <i>Ice Ess Fundamentals Review</i> , <b>2009</b> , 3, 25-32	0.1	17
569	Using a reliability capability maturity model to benchmark electronics companies. <i>International Journal of Quality and Reliability Management</i> , <b>2007</b> , 24, 547-563	2	17
568	Environmental Aging and Deadhesion of Polyimide Dielectric Films. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , <b>2004</b> , 126, 390-397	2	17
567	Physics-of-failure assessment of a cruise control module. <i>Microelectronics Reliability</i> , <b>1999</b> , 39, 1423-1444.	2	17
566	. <i>IEEE Transactions on Reliability</i> , <b>1988</b> , 37, 453-457	4.6	17
565	Metallized film capacitors used for EMI filtering: A reliability review. <i>Microelectronics Reliability</i> , <b>2019</b> , 92, 123-135	1.2	17
564	Reduction of Li-ion Battery Qualification Time Based on Prognostics and Health Management. <i>IEEE Transactions on Industrial Electronics</i> , <b>2019</b> , 66, 7310-7315	8.9	17
563	A Massively Parallel Approach to Real-Time Bearing Fault Detection Using Sub-Band Analysis on an FPGA-Based Multicore System. <i>IEEE Transactions on Industrial Electronics</i> , <b>2016</b> , 63, 6325-6335	8.9	16
562	A Weighted Deep Domain Adaptation Method for Industrial Fault Prognostics According to Prior Distribution of Complex Working Conditions. <i>IEEE Access</i> , <b>2019</b> , 7, 139802-139814	3.5	16
561	Tin whisker analysis of an automotive engine control unit. <i>Microelectronics Reliability</i> , <b>2014</b> , 54, 214-219	1.2	16
560	Life consumption monitoring for electronics prognostics		16
559	An avionics guide to uprating of electronic parts. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2000</b> , 23, 595-599		16
558	A critique of reliability prediction techniques for avionics applications. <i>Chinese Journal of Aeronautics</i> , <b>2018</b> , 31, 10-20	3.7	16
557	Failure of Polymer Aluminum Electrolytic Capacitors Under Elevated Temperature Humidity Environments. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2017</b> , 7, 745-750	1.7	15

556	Fault detection isolation and diagnosis of multi-axle speed sensors for high-speed trains. <i>Mechanical Systems and Signal Processing</i> , <b>2019</b> , 131, 183-198	7.8	15
555	An empirical model to describe performance degradation for warranty abuse detection in portable electronics. <i>Reliability Engineering and System Safety</i> , <b>2015</b> , 142, 92-99	6.3	15
554	Precursor monitoring approach for reliability assessment of cooling fans. <i>Journal of Intelligent Manufacturing</i> , <b>2012</b> , 23, 173-178	6.7	15
553	Health monitoring of lithium-ion batteries <b>2013</b> ,		15
552	Nondestructive Sensing of Interconnect Failure Mechanisms Using Time-Domain Reflectometry. <i>IEEE Sensors Journal</i> , <b>2011</b> , 11, 1236-1241	4	15
551	Considerations in the Use of the Laser Flash Method for Thermal Measurements of Thermal Interface Materials. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2011</b> , 1, 1015-1028	1.7	15
550	Failure Precursors for Polymer Resettable Fuses. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2010</b> , 10, 374-380	1.6	15
549	Design of Experiments for Board-Level Solder Joint Reliability of PBGA Package Under Various Manufacturing and Multiple Environmental Loading Conditions. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2009</b> , 32, 32-40		15
548	. <i>IEEE Transactions on Advanced Packaging</i> , <b>1997</b> , 20, 229-234		15
547	Early detection of interconnect degradation using RF impedance and SPRT <b>2008</b> ,		15
546	Regulations and market trends in lead-free and halogen-free electronics. <i>Circuit World</i> , <b>2007</b> , 33, 4-9	0.7	15
545	Process capability indices and product reliability. <i>Microelectronics Reliability</i> , <b>2001</b> , 41, 2067-2070	1.2	15
544	. <i>IEEE Access</i> , <b>2019</b> , 7, 24082-24095	3.5	14
543	Fault diagnosis of locomotive electro-pneumatic brake through uncertain bond graph modeling and robust online monitoring. <i>Mechanical Systems and Signal Processing</i> , <b>2015</b> , 50-51, 676-691	7.8	14
542	Phthalates in Electronics: The Risks and the Alternatives. <i>IEEE Access</i> , <b>2018</b> , 6, 6232-6242	3.5	14
541	<b>2011</b> ,		14
540	Health Monitoring and Prognostics of Electronics Subject to Vibration Load Conditions. <i>IEEE Sensors Journal</i> , <b>2009</b> , 9, 1479-1485	4	14
539	A hybrid prognostics and health management approach for condition-based maintenance <b>2009</b> ,		14

538	A fusion approach to IGBT power module prognostics <b>2009</b> ,		14
537	China's Efforts in Prognostics and Health Management. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2008</b> , 31, 509-518		14
536	Mahalanobis Distance and Projection Pursuit Analysis for Health Assessment of Electronic Systems. <i>Aerospace Conference Proceedings IEEE</i> , <b>2008</b> ,		14
535	Prognostics Assessment of Aluminum Support Structure on a Printed Circuit Board. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , <b>2006</b> , 128, 339-345	2	14
534	Evaluation of selected Japanese lead-free consumer electronics. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2003</b> , 26, 305-312		14
533	Mixed flowing gas studies of creep corrosion on plastic encapsulated microcircuit packages with noble metal pre-plated leadframes. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2005</b> , 5, 268-276 <sup>1.6</sup>		14
532	. <i>IEEE Transactions on Reliability</i> , <b>1993</b> , 42, 513-517	4.6	14
531	A fusion prognostics-based qualification test methodology for microelectronic products. <i>Microelectronics Reliability</i> , <b>2016</b> , 63, 320-324	1.2	14
530	Capacity-Fading Behavior Analysis for Early Detection of Unhealthy Li-Ion Batteries. <i>IEEE Transactions on Industrial Electronics</i> , <b>2021</b> , 68, 2659-2666	8.9	14
529	Detection of intermittent faults based on an optimally weighted moving average T2 control chart with stationary observations. <i>Automatica</i> , <b>2021</b> , 123, 109298	5.7	14
528	Fault Detection for Gas Turbine Hot Components Based on a Convolutional Neural Network. <i>Energies</i> , <b>2018</b> , 11, 2149	3.1	14
527	Autonomous health management for PMSM rail vehicles through demagnetization monitoring and prognosis control. <i>ISA Transactions</i> , <b>2018</b> , 72, 245-255	5.5	13
526	Comparative evaluation of metal and polymer ball bearings. <i>Wear</i> , <b>2013</b> , 302, 1499-1505	3.5	13
525	Size and constraint effects on interfacial fracture behavior of microscale solder interconnects. <i>Microelectronics Reliability</i> , <b>2013</b> , 53, 154-163	1.2	13
524	. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2015</b> , 15, 576-587	1.6	13
523	Opportunistic maintenance for multi-component systems considering structural dependence and economic dependence. <i>Journal of Systems Engineering and Electronics</i> , <b>2015</b> , 26, 493-501	1.3	13
522	A comparison analysis of air, liquid, and two-phase cooling of data centers <b>2012</b> ,		13
521	A multiple stage approach to mitigate the risks of telecommunication equipment under free air cooling conditions. <i>Energy Conversion and Management</i> , <b>2012</b> , 64, 424-432	10.6	13

520	Coupled Thermal-Stress Analysis for FC-BGA Packaging Reliability Design. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2010</b> , 33, 347-358		13
519	Benefits analysis of prognostics in systems <b>2010</b> ,		13
518	Prognostics and health monitoring for lithium-ion battery <b>2011</b> ,		13
517	Contact resistance and fretting corrosion of lead-free alloy coated electrical contacts. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2006</b> , 29, 402-410		13
516	Reliability prediction modeling of semiconductor light emitting device. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2003</b> , 3, 218-222	1.6	13
515	Effectiveness of conformal coatings on a PBGA subjected to unbiased high humidity, high temperature tests. <i>Microelectronics International</i> , <b>2000</b> , 17, 16-20	0.8	13
514	. <i>IEEE Transactions on Reliability</i> , <b>1993</b> , 42, 536-540	4.6	13
513	Electronic Circuit Health Estimation Through Kernel Learning. <i>IEEE Transactions on Industrial Electronics</i> , <b>2018</b> , 65, 1585-1594	8.9	12
512	Effects of moisture absorption on the electrical parameters of embedded capacitors with epoxy-BaTiO <sub>3</sub> nanocomposite dielectric. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2012</b> , 23, 1504-1510	2.1	12
511	Physics-of-failure approach for fan PHM in electronics applications <b>2010</b> ,		12
510	. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2010</b> , 10, 71-81	1.6	12
509	Prognostics-based product qualification <b>2009</b> ,		12
508	Design evaluation of a French refrigerator drawer system subjected to repeated food storage loads. <i>Engineering Failure Analysis</i> , <b>2009</b> , 16, 2224-2234	3.2	12
507	Effectiveness of embedded capacitors in reducing the number of surface mount capacitors for decoupling applications. <i>Circuit World</i> , <b>2010</b> , 36, 22-30	0.7	12
506	Failure prognostics of multilayer ceramic capacitors in temperature-humidity-bias conditions <b>2008</b> ,		12
505	The evaluation of copper migration during the die attach curing and second wire bonding process. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2005</b> , 28, 337-344		12
504	. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2001</b> , 24, 520-525		12
503	Deciphering the deluge of data. <i>IEEE Circuits and Devices: the Magazine of Electronic and Photonic Systems</i> , <b>2000</b> , 16, 26-34		12

502	. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2001</b> , 24, 721-728		12
501	A comparative assessment of gold plating thickness required for stationary electrical contacts. <i>Microelectronics Journal</i> , <b>1999</b> , 30, 217-222	1.8	12
500	. <i>IEEE Transactions on Advanced Packaging</i> , <b>1995</b> , 18, 150-153		12
499	Impedance-Based Condition Monitoring for Insulation Systems Used in Low-Voltage Electromagnetic Coils. <i>IEEE Transactions on Industrial Electronics</i> , <b>2017</b> , 64, 3748-3757	8.9	11
498	Simulation and Experimental Verification of Edge Blurring Phenomenon in Microdefect Inspection Based on High-Frequency Ultrasound. <i>IEEE Access</i> , <b>2019</b> , 7, 11515-11525	3.5	11
497	A Life Model for Supercapacitors. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2015</b> , 15, 519-528	1.6	11
496	Conflict Minerals in Electronic Systems: An Overview and Critique of Legal Initiatives. <i>Science and Engineering Ethics</i> , <b>2016</b> , 22, 1375-1389	3.1	11
495	Nvidia® GPU failures: A case for prognostics and health management. <i>Microelectronics Reliability</i> , <b>2012</b> , 52, 953-957	1.2	11
494	A Bayesian Hidden Markov Model-based approach for anomaly detection in electronic systems <b>2013</b> ,		11
493	Rolling element bearing fault diagnosis using simulated annealing optimized spectral kurtosis <b>2013</b> ,		11
492	A Two-Level Inspection Model With Technological Insertions. <i>IEEE Transactions on Reliability</i> , <b>2012</b> , 61, 479-490	4.6	11
491	Reliability design and case study of refrigerator parts subjected to repetitive loads under consumer usage conditions. <i>Engineering Failure Analysis</i> , <b>2011</b> , 18, 1818-1830	3.2	11
490	Conductive filament formation in printed circuit boards: effects of reflow conditions and flame retardants. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2011</b> , 22, 1602-1615	2.1	11
489	Encapsulation Process Technology <b>2009</b> , 129-179		11
488	Reliability design of residential sized refrigerators subjected to repetitive random vibration loads during rail transport. <i>Engineering Failure Analysis</i> , <b>2011</b> , 18, 1322-1332	3.2	11
487	Isothermal aging effects on flex cracking of multilayer ceramic capacitors with standard and flexible terminations. <i>Microelectronics Reliability</i> , <b>2007</b> , 47, 2215-2225	1.2	11
486	Key reliability concerns with lead-free connectors. <i>Microelectronics Reliability</i> , <b>2008</b> , 48, 1613-1627	1.2	11
485	Assessment of risk resulting from unattached tin whisker bridging. <i>Circuit World</i> , <b>2007</b> , 33, 5-8	0.7	11

484	Length Distribution Analysis for Tin Whisker Growth. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2007</b> , 30, 36-40		11
483	Temperature dependence of microelectronic device failures. <i>Quality and Reliability Engineering International</i> , <b>1990</b> , 6, 275-284	2.6	11
482	Visual inspection of steel surface defects based on domain adaptation and adaptive convolutional neural network. <i>Mechanical Systems and Signal Processing</i> , <b>2021</b> , 153, 107541	7.8	11
481	Reliability design and case study of the domestic compressor subjected to repetitive internal stresses. <i>Reliability Engineering and System Safety</i> , <b>2020</b> , 193, 106604	6.3	11
480	CP-Less OFDM With Alignment Signals for Enhancing Spectral Efficiency, Reducing Latency, and Improving PHY Security of 5G Services. <i>IEEE Access</i> , <b>2018</b> , 6, 63649-63663	3.5	11
479	The significance of aqueous binders in lithium-ion batteries. <i>Renewable and Sustainable Energy Reviews</i> , <b>2021</b> , 147, 111227	16.2	11
478	Joint Estimation of Inconsistency and State of Health for Series Battery Packs. <i>Automotive Innovation</i> , <b>2021</b> , 4, 103-116	1.7	11
477	Sparse auto-encoder with regularization method for health indicator construction and remaining useful life prediction of rolling bearing. <i>Measurement Science and Technology</i> , <b>2020</b> , 31, 105005	2	10
476	Data-driven reliability analysis of Boeing 787 Dreamliner. <i>Chinese Journal of Aeronautics</i> , <b>2020</b> , 33, 1969-1979	3.79	10
475	Evaluating Characteristics of Electrostatic Discharge (ESD) Events in Wearable Medical Devices: Comparison With the IEC 61000-4-2 Standard. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2018</b> , 60, 1304-1312	2	10
474	State of charge estimation based on a thermal coupling simplified first-principles model for lithium-ion batteries. <i>Journal of Energy Storage</i> , <b>2019</b> , 25, 100838	7.8	10
473	Strain-Range-Based Solder Life Predictions Under Temperature Cycling With Varying Amplitude and Mean. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2014</b> , 14, 351-357	1.6	10
472	Modeling the Electrical Conduction in Epoxy/BaTiO <sub>3</sub> Nanocomposites. <i>Journal of Electronic Materials</i> , <b>2013</b> , 42, 1101-1107	1.9	10
471	Effects of thermal cycling on rare earth (Pr)-induced Sn whisker/hillock growth. <i>Materials Letters</i> , <b>2013</b> , 98, 78-81	3.3	10
470	Optimum Cooling of Data Centers <b>2014</b> ,		10
469	. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2010</b> , 33, 240-245		10
468	Prognostics of Multilayer Ceramic Capacitors Via the Parameter Residuals. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2012</b> , 12, 49-57	1.6	10
467	Effect of Lead-Free Soldering on Key Material Properties of FR-4 Printed Circuit Board Laminates. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2009</b> , 32, 272-280		10

466	Standards for Tin Whisker Test Methods on Lead-Free Components. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2009</b> , 32, 216-219		10
465	The nature of the antigen. <i>Advances in Protein Chemistry</i> , <b>1996</b> , 49, 289-328		10
464	Detection of solder joint degradation using RF impedance analysis <b>2008</b> ,		10
463	Prognostics and Health Monitoring of Electronics <b>2007</b> ,		10
462	Reliability assessment of electronic components exposed to long-term non-operating conditions. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>1998</b> , 21, 352-359		10
461	Lifetime resistance model of bare metal electrical contacts. <i>IEEE Transactions on Advanced Packaging</i> , <b>1999</b> , 22, 60-67		10
460	Sensor System Selection for Prognostics and Health Monitoring <b>2008</b> ,		10
459	Virtual Remaining Life Assessment of Electronic Hardware Subjected to Shock and Random Vibration Life Cycle Loads. <i>Journal of the IEST</i> , <b>2007</b> , 50, 86-97	0.2	10
458	Machine Learning: Fundamentals <b>2018</b> , 85-109		10
457	Methods for fault diagnosis of high-speed railways: A review. <i>Proceedings of the Institution of Mechanical Engineers, Part O: Journal of Risk and Reliability</i> , <b>2019</b> , 233, 908-922	0.8	9
456	Thermal Fatigue Reliability Analysis and Structural Optimization Based on a Robust Method for Microelectronics FBGA Packages. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2015</b> , 15, 206-213 <sup>1.6</sup>		9
455	Artificial Intelligence Trends Based on the Patents Granted by the United States Patent and Trademark Office. <i>IEEE Access</i> , <b>2020</b> , 8, 81633-81643	3.5	9
454	Analysis of the Kinetics of Electrochemical Migration on Printed Circuit Boards Using Nernst-Planck Transport Equation. <i>Electrochimica Acta</i> , <b>2014</b> , 142, 1-10	6.7	9
453	A multi-attribute classification fusion system for insulated gate bipolar transistor diagnostics. <i>Microelectronics Reliability</i> , <b>2013</b> , 53, 1117-1129	1.2	9
452	Review of offshore wind turbine failures and fault prognostic methods <b>2012</b> ,		9
451	Reduction of motion artifacts in electrocardiogram monitoring using an optical sensor. <i>Biomedical Instrumentation and Technology</i> , <b>2011</b> , 45, 155-63	0.4	9
450	Anomaly detection of non punch through insulated gate bipolar transistors (IGBT) by robust covariance estimation techniques <b>2010</b> ,		9
449	Using real options to manage condition-based maintenance enabled by PHM <b>2011</b> ,		9

448	An analytical model of the RF impedance change due to solder joint cracking <b>2011</b> ,		9
447	Identification of interconnect failure mechanisms using RF impedance analysis <b>2009</b> ,		9
446	Computer Usage Monitoring for Design and Reliability Tests. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2009</b> , 32, 550-556		9
445	Effect of Solder Joint Degradation on RF Impedance <b>2008</b> ,		9
444	Reliability of pressure-sensitive adhesive tapes for heat sink attachment in air-cooled electronic assemblies. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2004</b> , 4, 650-657	1.6	9
443	Why Gold Flash Can Be Detrimental to Long-Term Reliability. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , <b>2004</b> , 126, 37-40	2	9
442	Manufacturer assessment procedure and criteria for parts selection and management. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2001</b> , 24, 351-358		9
441	Parameter recharacterization: a method of thermal uprating. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2001</b> , 24, 729-737		9
440	Mast cell stimulation by co-clustering the type I Fc epsilon-receptors with mast cell function-associated antigens. <i>Immunology Letters</i> , <b>1999</b> , 68, 71-8	4.1	9
439	Multi-Objective Optimization Design of a Notch Filter Based on Improved NSGA-II for Conducted Emissions. <i>IEEE Access</i> , <b>2020</b> , 8, 83213-83223	3.5	9
438	Prognostics of lithium-ion batteries based on different dimensional state equations in the particle filtering method. <i>Transactions of the Institute of Measurement and Control</i> , <b>2017</b> , 39, 1537-1546	1.8	8
437	. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2015</b> , 15, 500-510	1.6	8
436	An analytical model for the CC-CV charge of Li-ion batteries with application to degradation analysis. <i>Journal of Energy Storage</i> , <b>2020</b> , 29, 101342	7.8	8
435	An improved empirical wavelet transform method for rolling bearing fault diagnosis. <i>Science China Technological Sciences</i> , <b>2020</b> , 63, 2231-2240	3.5	8
434	. <i>IEEE Access</i> , <b>2019</b> , 7, 71131-71141	3.5	8
433	Cost Optimization for Canary-Equipped Electronic Systems in Terms of Inventory Control and Maintenance Decisions. <i>IEEE Transactions on Reliability</i> , <b>2012</b> , 61, 466-478	4.6	8
432	. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2013</b> , 13, 146-155	1.6	8
431	Long term storage reliability of antifuse field programmable gate arrays. <i>Microelectronics Reliability</i> , <b>2013</b> , 53, 2052-2056	1.2	8

430	Cyclic feature suppression for physical layer security. <i>Physical Communication</i> , <b>2017</b> , 25, 588-597	2.2	8
429	Electrical Shorting Propensity of Tin Whiskers. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2010</b> , 33, 205-211		8
428	Interconnect reliability assessment of high power Light Emitting Diodes (LEDs) through simulation <b>2010</b> ,		8
427	<b>2009</b> ,		8
426	Solder Ball Attachment Assessment of Reballled Plastic Ball Grid Array Packages. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2009</b> , 32, 901-908		8
425	Cooling fan bearing fault identification using vibration measurement <b>2011</b> ,		8
424	An assessment of the Qualified Manufacturer List (QML). <i>IEEE Aerospace and Electronic Systems Magazine</i> , <b>1997</b> , 12, 39-42	2.4	8
423	A critique of the Reliability Analysis Center failure-rate-model for plastic encapsulated microcircuits. <i>IEEE Transactions on Reliability</i> , <b>1998</b> , 47, 110-113	4.6	8
422	Anisotropic Conductive Adhesives for Flip-Chip Interconnects. <i>Journal of Adhesion Science and Technology</i> , <b>2008</b> , 22, 871-892	2	8
421	Contact Resistance Estimation for Time-Dependent Silicone Elastomer Matrix of Land Grid Array Socket. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2007</b> , 30, 81-85		8
420	Tin Whiskers: How to Mitigate and Manage the Risks <b>2007</b> ,		8
419	Assessment of Ni/Pd/AuPd and Ni/Pd/AuAg Preplated Leadframe Packages Subject to Electrochemical Migration and Mixed Flowing Gas Tests. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2006</b> , 29, 818-826		8
418	A variant of conductive filament formation failures in PWBs with 3 and 4 mil spacings. <i>Circuit World</i> , <b>2006</b> , 32, 11-18	0.7	8
417	Diffusion and absorption of corrosive gases in electronic encapsulants. <i>Microelectronics Reliability</i> , <b>2003</b> , 43, 635-643	1.2	8
416	Effects and interactions of design parameters for gold-plated electric contacts. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2000</b> , 11, 209-218	2.1	8
415	An investigation of the contact behavior of electric distributed filament contacts. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>1998</b> , 21, 604-609		8
414	Modeling the Effects of Mixed Flowing Gas (MFG) Corrosion and Stress Relaxation on Contact Interface Resistance. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , <b>1993</b> , 115, 404-409	2	8
413	. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>1994</b> , 17, 610-615		8

412	. <i>IEEE Transactions on Electron Devices</i> , <b>1992</b> , 39, 1075-1079	2.9	8
411	Physics-of-Failure: An Approach to Reliable Product Development. <i>Journal of the Institute of Environmental Sciences</i> , <b>1995</b> , 38, 30-34		8
410	The Counterfeit Electronics Problem. <i>Open Journal of Social Sciences</i> , <b>2013</b> , 01, 12-16	0.2	8
409	A Local Adaptive Minority Selection and Oversampling Method for Class-Imbalanced Fault Diagnostics in Industrial Systems. <i>IEEE Transactions on Reliability</i> , <b>2020</b> , 69, 1195-1206	4.6	8
408	Novel Parametric Circuit Modeling for Li-Ion Batteries. <i>Energies</i> , <b>2016</b> , 9, 539	3.1	8
407	A Deep Forest-Based Fault Diagnosis Scheme for Electronics-Rich Analog Circuit Systems. <i>IEEE Transactions on Industrial Electronics</i> , <b>2021</b> , 68, 10087-10096	8.9	8
406	Derating Guidelines for Lithium-Ion Batteries. <i>Energies</i> , <b>2018</b> , 11, 3295	3.1	8
405	A perspective of the IPC report on lead-free electronics in military/aerospace applications. <i>Microelectronics Reliability</i> , <b>2017</b> , 69, 66-70	1.2	7
404	Batteries in Portable Electronic Devices: A User's Perspective. <i>IEEE Industrial Electronics Magazine</i> , <b>2017</b> , 11, 35-44	6.2	7
403	A Domain Adaptive Convolutional LSTM Model for Prognostic Remaining Useful Life Estimation Under Variant Conditions <b>2019</b> ,		7
402	Life cycle trends of electronic materials, processes and components. <i>Microelectronics Reliability</i> , <b>2019</b> , 99, 262-276	1.2	7
401	In Situ Interconnect Failure Prediction Using Canaries. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2014</b> , 14, 826-832	1.6	7
400	Fault diagnostic opportunities for solenoid operated valves using physics-of-failure analysis <b>2014</b> ,		7
399	Reliability and failure analysis of Lithium Ion batteries for electronic systems <b>2012</b> ,		7
398	Return on investment associated with PHM applied to an LED lighting system <b>2013</b> ,		7
397	Assessment of Solder-Dipping as a Tin Whisker Mitigation Strategy. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2011</b> , 1, 957-963	1.7	7
396	Study of ensemble learning-based fusion prognostics <b>2010</b> ,		7
395	Evaluation of the microstructure and whisker growth in Sn <sub>3</sub> NiCu solder with Pr content. <i>Journal of Materials Research</i> , <b>2012</b> , 27, 1887-1894	2.5	7

394	Reliability of gull-wing and leadless packages subjected to temperature cycling after rework. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2012</b> , 12, 510-519	1.6	7
393	Baseline Performance of Notebook Computers Under Various Environmental and Usage Conditions for Prognostics. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2009</b> , 32, 667-676		7
392	Upgrading of electronic parts to address obsolescence. <i>Microelectronics International</i> , <b>2006</b> , 23, 32-36	0.8	7
391	. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2007</b> , 7, 200-208	1.6	7
390	Energetic Material/ Systems Prognostics <b>2007</b> ,		7
389	Room temperature soldering of microelectronic components for enhanced thermal performance		7
388	The Influence of Substrate Enhancement on Moisture Sensitivity Level (MSL) Performance for Green PBGA Packages. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2006</b> , 29, 522-527		7
387	. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2004</b> , 27, 493-498		7
386	. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2003</b> , 26, 682-686		7
385	. <i>IEEE Transactions on Semiconductor Manufacturing</i> , <b>2002</b> , 15, 253-259	2.6	7
384	Tipping the scales in your favor when upgrading. <i>IEEE Circuits and Devices: the Magazine of Electronic and Photonic Systems</i> , <b>1999</b> , 15, 15-23		7
383	Environmental Scanning Electron Microscopic Investigation of Failure Mechanisms in Electronic Packages. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , <b>1995</b> , 117, 225-229	2	7
382	Computed Tomography Analysis of Li-Ion Battery Case Ruptures. <i>Fire Technology</i> , <b>2020</b> , 56, 2565-2578	3	7
381	Early detection of anomalous degradation behavior in lithium-ion batteries. <i>Journal of Energy Storage</i> , <b>2020</b> , 32, 101710	7.8	7
380	Unsupervised Locality-Preserving Robust Latent Low-Rank Recovery-Based Subspace Clustering for Fault Diagnosis. <i>IEEE Access</i> , <b>2018</b> , 6, 52345-52354	3.5	7
379	Hybrid remaining useful life prediction method. A case study on railway D-cables. <i>Reliability Engineering and System Safety</i> , <b>2021</b> , 213, 107746	6.3	7
378	Parameter updating method of a simplified first principles-thermal coupling model for lithium-ion batteries. <i>Applied Energy</i> , <b>2019</b> , 256, 113924	10.7	6
377	Water-Resistant Smartphone Technologies. <i>IEEE Access</i> , <b>2019</b> , 7, 42757-42773	3.5	6

376	Maximizing Network Resilience against Malicious Attacks. <i>Scientific Reports</i> , <b>2019</b> , 9, 2261	4.9	6
375	Special Issue on Robust Design and Reliability of Power Electronics, IEEE Transactions on Power Electronics, May 2015. <i>IEEE Transactions on Power Electronics</i> , <b>2015</b> , 30, 2373-2374	7.2	6
374	Two-level fault diagnosis RBF networks for auto-transformer rectifier units using multi-source features. <i>Journal of Power Electronics</i> , <b>2020</b> , 20, 754-763	0.9	6
373	The effect of epoxy/glass interfaces on CAF failures in printed circuit boards. <i>Microelectronics Reliability</i> , <b>2018</b> , 82, 235-243	1.2	6
372	Detection of capacitor electrolyte residues with FTIR in failure analysis. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2014</b> , 25, 635-644	2.1	6
371	In-situ monitoring and anomaly detection for LED packages using a Mahalanobis distance approach <b>2015</b> ,		6
370	Anomaly detection for chromaticity shift of high power white LED with mahalanobis distance approach <b>2012</b> ,		6
369	Comparison of Printed Circuit Board Property Variations in Response to Simulated Lead-Free Soldering. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2010</b> , 33, 98-111		6
368	Energy harvesting using RF MEMS <b>2010</b> ,		6
367	Effect of Moisture on Thermal Properties of Halogen-Free and Halogenated Printed-Circuit-Board Laminates. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2011</b> , 11, 66-75	1.6	6
366	Reliability of Embedded Planar Capacitors With Epoxy $\text{BaTiO}_3$ Composite Dielectric During TemperatureHumidityBias Tests. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2012</b> , 12, 86-93	1.6	6
365	Accelerated Temperature and Voltage Stress Tests of Embedded Planar Capacitors With Epoxy $\text{BaTiO}_3$ Composite Dielectric. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , <b>2012</b> , 134,	2	6
364	Physics of Failure Based Virtual Testing of Communications Hardware <b>2009</b> ,		6
363	The Measurement of Ion Diffusion in Epoxy Molding Compounds by Dynamic Secondary Ion Mass Spectroscopy. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2008</b> , 31, 527-535		6
362	IDDQ trending as a precursor to semiconductor failure <b>2008</b> ,		6
361	A hybrid prognostics methodology for electronic products <b>2008</b> ,		6
360	Assessment of Thermomechanical Damage of Electronic Parts Due to Solder Dipping as a Postmanufacturing Process. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2007</b> , 30, 128-137		6
359	WEEE, RoHS, and what you must do to get ready for lead-free electronics		6

358	. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2006</b> , 29, 364-370		6
357	<b>2004</b> ,		6
356	Component Socket Properties <b>2004</b> , 21-44		6
355	Load characterization during transportation. <i>Microelectronics Reliability</i> , <b>2004</b> , 44, 333-338	1.2	6
354	. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2003</b> , 3, 39-43	1.6	6
353	Part assessment guidelines and criteria for parts selection and management. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>2001</b> , 24, 339-350		6
352	The realism of FAA reliability-safety requirements and alternatives. <i>IEEE Aerospace and Electronic Systems Magazine</i> , <b>1998</b> , 13, 16-20	2.4	6
351	Wide-dynamic-range APS star tracker <b>1996</b> , 2654, 82		6
350	Temperature Dependence of the Mechanical Properties of GaAs Wafers. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , <b>1991</b> , 113, 331-336	2	6
349	A modified Powell method for six-degrees-of-freedom platform kinematics. <i>Computers and Structures</i> , <b>1990</b> , 34, 485-491	4.5	6
348	CALCE/RAMCAD for Electronics. <i>IEEE Transactions on Reliability</i> , <b>1987</b> , R-36, 501-506	4.6	6
347	An Investigation into PWB Component-Placement Tradeoffs. <i>IEEE Transactions on Reliability</i> , <b>1987</b> , R-36, 524-527	4.6	6
346	Auditing the Reliability Capability of Electronics Manufacturers <b>2003</b> ,		6
345	Weighted Entropy Minimization Based Deep Conditional Adversarial Diagnosis Approach Under Variable Working Conditions. <i>IEEE/ASME Transactions on Mechatronics</i> , <b>2021</b> , 26, 2440-2450	5.5	6
344	Failure precursors for insulated gate bipolar transistors (IGBTs) <b>2008</b> ,		6
343	Reliability analysis of multilayer polymer aluminum electrolytic capacitors. <i>Microelectronics Reliability</i> , <b>2020</b> , 112, 113725	1.2	6
342	Evaluation of Batteries for Safe Air Transport. <i>Energies</i> , <b>2016</b> , 9, 340	3.1	6
341	Battery Stress Factor Ranking for Accelerated Degradation Test Planning Using Machine Learning. <i>Energies</i> , <b>2021</b> , 14, 723	3.1	6

340	A Joint Distribution-Based Testability Metric Estimation Model for Unreliable Tests. <i>IEEE Access</i> , <b>2018</b> , 6, 42566-42577	3.5	6
339	Effects of Sn addition on the microstructure and properties of Bi-1Ag high-temperature solder. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2018</b> , 29, 12028-12035	2.1	6
338	An ensemble learning-based fault diagnosis method for rotating machinery <b>2017</b> ,		5
337	The Explosive Nature of Tab Burrs in Li-Ion Batteries. <i>IEEE Access</i> , <b>2019</b> , 7, 45978-45982	3.5	5
336	A Prognostics and Health Management Based Method for Refurbishment Decision Making for Electromechanical Systems. <i>IFAC-PapersOnLine</i> , <b>2015</b> , 48, 454-459	0.7	5
335	. <i>IEEE Access</i> , <b>2020</b> , 8, 101859-101866	3.5	5
334	Improved electromagnetic coil insulation health monitoring using equivalent circuit model analysis. <i>International Journal of Electrical Power and Energy Systems</i> , <b>2020</b> , 119, 105829	5.1	5
333	Failure mechanisms in encapsulated copper wire-bonded devices <b>2016</b> ,		5
332	The effect of temperature on the electrochemistry in Lithium-ion batteries <b>2014</b> ,		5
331	Oversampling advances in millimeter-wave scan imaging using inexpensive neon indicator lamp detectors. <i>Optical Engineering</i> , <b>2013</b> , 52, 063202	1.1	5
330	Evaluating covariance in prognostic and system health management applications. <i>Mechanical Systems and Signal Processing</i> , <b>2015</b> , 58-59, 206-217	7.8	5
329	Copper Wire Bonding <b>2014</b> , 1-9		5
328	Effect of Isothermal Aging on Microstructure and Creep Properties of SAC305 Solder: A Micromechanics Approach <b>2013</b> ,		5
327	Solder Joint Reliability of SnAgCu Solder Refinished Components Under Temperature Cycling Test. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2011</b> , 1, 798-808	1.7	5
326	Effects of Moisture Content on Dielectric Constant and Dissipation Factor of Printed Circuit Board Materials. <i>ECS Transactions</i> , <b>2010</b> , 27, 227-236	1	5
325	Stress Relaxation Testing of Stamped Metal Land-Grid-Array Sockets. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2010</b> , 10, 55-61	1.6	5
324	Health assessment and prognostics of electronic products <b>2009</b> ,		5
323	Plastic Encapsulant Materials <b>2009</b> , 47-127		5

322	. <i>IEEE Transactions on Reliability</i> , <b>2009</b> , 58, 634-640	4.6	5
321	Assessing the Reliability of Elastomer Sockets in Temperature Environments. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2009</b> , 9, 80-86	1.6	5
320	High Cycle Cyclic Torsion Fatigue of PBGA Pb-Free Solder Joints. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2008</b> , 31, 309-314		5
319	. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2007</b> , 30, 716-723		5
318	Predicting the Reliability of Electronic Products <b>2007</b> ,		5
317	. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2006</b> , 29, 804-808		5
316	Developments in ambulatory electrocardiography. <i>Biomedical Instrumentation and Technology</i> , <b>2006</b> , 40, 238-45	0.4	5
315	Measurement of Hygroscopic Swelling in Mold Compounds and Its Effect on PEM Reliability <b>2003</b> , 497		5
314	. <i>IEEE Transactions on Reliability</i> , <b>2004</b> , 53, 279-283	4.6	5
313	An investigation of the mechanical behavior of conductive elastomer interconnects. <i>Microelectronics Reliability</i> , <b>2001</b> , 41, 281-286	1.2	5
312	. <i>IEEE Antennas and Propagation Magazine</i> , <b>2002</b> , 44, 30-39	1.7	5
311	A kinetic model for noble plated electrical contact behavior. <i>Scripta Materialia</i> , <b>1999</b> , 42, 1-8	5.6	5
310	New findings in the occurrence of false-healing in plastic encapsulated microcircuits using scanning acoustic microscopy. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>1999</b> , 22, 266-269		5
309	Imbalanced bearing fault diagnosis under variant working conditions using cost-sensitive deep domain adaptation network. <i>Expert Systems With Applications</i> , <b>2022</b> , 193, 116459	7.8	5
308	Life-cycle parameter identification method of an electrochemical model for lithium-ion battery pack. <i>Journal of Energy Storage</i> , <b>2021</b> , 47, 103591	7.8	5
307	Effects of Extended Dwell Time on Thermal Fatigue Life of Ceramic Chip Resistors. <i>International Symposium on Microelectronics</i> , <b>2012</b> , 2012, 000127-000135	0.2	5
306	Electronic Hardware Reliability. <i>The Electrical Engineering Handbook</i> , <b>2000</b> ,		5
305	Protection Devices in Commercial 18650 Lithium-Ion Batteries. <i>IEEE Access</i> , <b>2021</b> , 9, 66687-66695	3.5	5

304	Reliability Analysis of Repairable Systems Based on a Two-Segment Bathtub-Shaped Failure Intensity Function. <i>IEEE Access</i> , <b>2018</b> , 6, 52374-52384	3.5	5
303	Evaluation of Present Accelerated Temperature Testing and Modeling of Batteries. <i>Applied Sciences (Switzerland)</i> , <b>2018</b> , 8, 1786	2.6	5
302	An Assessment of Validity of the Bathtub Model Hazard Rate Trends in Electronics. <i>IEEE Access</i> , <b>2021</b> , 9, 10282-10290	3.5	5
301	An evaluation of dwell time and mean cyclic temperature parameters in the Engelmaier model. <i>Microelectronics Reliability</i> , <b>2015</b> , 55, 582-587	1.2	4
300	<b>2015</b> ,		4
299	A Unique Failure Mechanism in the Nexus 6P Lithium-Ion Battery. <i>Energies</i> , <b>2018</b> , 11, 841	3.1	4
298	Effects of Voiding on the Degradation of Microvias in High Density Interconnect Printed Circuit Boards Under Thermomechanical Stresses. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2014</b> , 4, 1374-1379	1.7	4
297	<b>2014</b> ,		4
296	. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2012</b> , 12, 420-427	1.6	4
295	A canary device based approach for prognosis of Ball Grid Array packages <b>2012</b> ,		4
294	Influence of Molding Compound on Leakage Current in MOS Transistors. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2011</b> , 1, 1054-1063	1.7	4
293	Printed Circuit Board Laminates <b>2011</b> , 1		4
292	Complex system maintainability verification with limited samples. <i>Microelectronics Reliability</i> , <b>2011</b> , 51, 294-299	1.2	4
291	Validation of reliability capability evaluation model using a quantitative assessment process. <i>International Journal of Quality and Reliability Management</i> , <b>2010</b> , 27, 938-952	2	4
290	Microstructural Analysis of Reworked Ball Grid Array Assemblies Under Thermomechanical Loading Conditions. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2010</b> , 10, 276-286	1.6	4
289	<b>2010</b> ,		4
288	Automatic data mining for telemetry database of computer systems. <i>Microelectronics Reliability</i> , <b>2011</b> , 51, 263-269	1.2	4
287	A case study on battery life prediction using particle filtering <b>2012</b> ,		4

286	Highly Accelerated Life Testing of Embedded Planar Capacitors With Epoxy- $\text{BaTiO}_3$ Nanocomposite Dielectric. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2012</b> , 2, 1580-1586	1.7	4
285	A framework for cost-effective and accurate maintenance combining CBM RCM and data fusion <b>2009</b> ,		4
284	Microstructural Analysis of Reballled Tin-Lead, Lead-Free, and Mixed Ball Grid Array Assemblies Under Temperature Cycling Test. <i>Journal of Electronic Materials</i> , <b>2010</b> , 39, 1218-1232	1.9	4
283	Maxima-SPRT methodology for health monitoring of contact resistance in IC sockets <b>2008</b> ,		4
282			4
281	Extending the limits of air-cooling in microelectronic equipment		4
280	Effects of Printed Circuit Board Materials on Lead-free Interconnect Durability		4
279	Tracking semiconductor part changes through the part supply chain. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2002</b> , 25, 230-238		4
278	Conductive filament formation: a potential reliability issue in laminated printed circuit cards with hollow fibers. <i>IEEE Transactions on Electronics Packaging Manufacturing</i> , <b>1999</b> , 22, 80-84		4
277	THE EFFECT OF MANUFACTURING AND DESIGN PROCESS VARIABILITIES ON THE FATIGUE LIFE OF THE HIGH DENSITY INTERCONNECT VIAS. <i>Journal of Electronics Manufacturing</i> , <b>1995</b> , 05, 111-119		4
276	A viscoelastic constitutive model for constant rate loading at different relative humidities. <i>Mechanics of Materials</i> , <b>1991</b> , 11, 337-345	3.3	4
275	Failure Prediction of Multilayer Ceramic Capacitors (MLCCs) under Temperature-Humidity-Bias Testing Conditions Using Non-Linear Modeling. <i>Journal of the Microelectronics and Packaging Society</i> , <b>2013</b> , 20, 7-10		4
274	Electronic Hardware Reliability. <i>The Electrical Engineering Handbook</i> , <b>2006</b> , 4-1-4-22		4
273	Copper Trace Fatigue Life Modeling for Rigid Electronic Assemblies. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2021</b> , 21, 79-86	1.6	4
272	Role of the rest period in capacity fade of Graphite/LiCoO <sub>2</sub> batteries. <i>Journal of Power Sources</i> , <b>2021</b> , 484, 229246	8.9	4
271	Charging induced electrode layer fracturing of 18650 lithium-ion batteries. <i>Journal of Power Sources</i> , <b>2021</b> , 484, 229260	8.9	4
270	A Machine Learning Degradation Model for Electrochemical Capacitors Operated at High Temperature. <i>IEEE Access</i> , <b>2021</b> , 9, 25544-25553	3.5	4
269	Lithium-iron-phosphate battery electrochemical modelling under a wide range of ambient temperatures. <i>Journal of Electroanalytical Chemistry</i> , <b>2021</b> , 882, 115041	4.1	4

268	Creating Self-Aware Low-Voltage Electromagnetic Coils for Incipient Insulation Degradation Monitoring for Smart Manufacturing. <i>IEEE Access</i> , <b>2018</b> , 6, 69860-69868	3.5	4
267	Machine Learning: Anomaly Detection <b>2018</b> , 131-162		4
266	Lithium-ion battery state-of-charge estimation based on deconstructed equivalent circuit at different open-circuit voltage relaxation times. <i>Journal of Zhejiang University: Science A</i> , <b>2017</b> , 18, 256-267 <sup>1</sup>		3
265	. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2019</b> , 19, 176-188	1.6	3
264	Evaluating the Impact of Dwell Time on Solder Interconnect Durability Under Bending Loads. <i>Journal of Electronic Materials</i> , <b>2015</b> , 44, 4549-4556	1.9	3
263	. <i>IEEE Access</i> , <b>2020</b> , 8, 21326-21332	3.5	3
262	Risk of tin whiskers in the nuclear industry. <i>Microelectronics Reliability</i> , <b>2018</b> , 81, 22-30	1.2	3
261	How Poor Reliability Affects Warranties: An Analysis of General Motors Powertrain Warranty Reduction. <i>IEEE Access</i> , <b>2018</b> , 6, 15065-15074	3.5	3
260	Evaluation of ENEPIG and Immersion Silver Surface Finishes Under Drop Loading. <i>Journal of Electronic Materials</i> , <b>2016</b> , 45, 391-402	1.9	3
259	New Minimum Relative Humidity Requirements Are Expected to Lead to More Medical Device Failures. <i>Journal of Medical Systems</i> , <b>2016</b> , 40, 58	5.1	3
258	Machine Learning: Data Pre-processing <b>2018</b> , 111-130		3
257	Modeling the Rate-Dependent Durability of Reduced-Ag SAC Interconnects for Area Array Packages Under Torsion Loads. <i>Journal of Electronic Materials</i> , <b>2013</b> , 42, 2606-2614	1.9	3
256	A circuit-centric approach to electronic system-level diagnostics and prognostics <b>2013</b> ,		3
255	Prognostics-based product warranties <b>2013</b> ,		3
254	A dual-level approach for lithium-ion battery RUL prognosis <b>2015</b> ,		3
253	Use of temperature as a health monitoring tool for solder interconnect degradation in electronics <b>2012</b> ,		3
252	<b>2012</b> ,		3
251	Prognostics of Embedded Planar Capacitors Under Temperature and Voltage Aging <b>2010</b> ,		3

250	Prognostics-based health management for free air cooling of data centers <b>2010,</b>		3
249	. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2011</b> , 11, 391-400	1.6	3
248	. <i>Reliability and Maintainability Symposium (RAMS), Annual</i> , <b>2009,</b>		3
247	Remaining useful performance analysis of batteries <b>2011,</b>		3
246	Influence of parameter initialization on battery life prediction for online applications <b>2012,</b>		3
245	Investigation on Mechanism of Creep Corrosion of Immersion Silver Finished Printed Circuit Board by Clay Tests <b>2009,</b>		3
244	Impact of Thermal Aging on the Growth of Cu-Sn Intermetallic Compounds in Pb-Free Solder Joints in 2512 Resistors <b>2009,</b>		3
243	Addressing Obsolescence—the Upgrading Option. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2008</b> , 31, 741-745		3
242	Assessing the operating temperature and relative humidity environment of IC sockets in enterprise servers <b>2008,</b>		3
241	Learning from the migration to lead-free solder. <i>Soldering and Surface Mount Technology</i> , <b>2006</b> , 18, 14-18.4		3
240	How China is closing the semiconductor technology gap. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2004</b> , 27, 616-619		3
239	Thermal assessment of glass-metal composition plasma display panels using design of experiments. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2004</b> , 27, 210-216		3
238	Engineered Reliability for Intelligent Well Systems <b>2001,</b>		3
237	Handbook of Electronic Package Design. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , <b>2000</b> , 122, 178-179	2	3
236	Failure Site Transition During Drop Testing of Printed Wiring Assemblies <b>2005,</b>		3
235	Detection and Isolation of Wheelset Intermittent Over-Creeps for Electric Multiple Units Based on a Weighted Moving Average Technique. <i>IEEE Transactions on Intelligent Transportation Systems</i> , <b>2020</b> , 1-14	6.1	3
234	Failures in Electronic Assemblies and Devices <b>2001,</b> 204-232		3
233	The Telecom Industry and Data Centers <b>2014,</b> 1-8		3

232	Board-Level Lifetime Prediction for Power Board of Balise Transmission Module in High-Speed Railways. <i>IEEE Access</i> , <b>2020</b> , 8, 135011-135024	3.5	3
231	Artificial Intelligence-Related Research Funding by the U.S. National Science Foundation and the National Natural Science Foundation of China. <i>IEEE Access</i> , <b>2020</b> , 8, 183448-183459	3.5	3
230	Generalized sparse filtering for rotating machinery fault diagnosis. <i>Journal of Supercomputing</i> , <b>2021</b> , 77, 3402-3421	2.5	3
229	Computing Lifetime Distributions and Reliability for Systems With Outsourced Components: A Case Study. <i>IEEE Access</i> , <b>2018</b> , 6, 31359-31366	3.5	3
228	State of health prediction based on multi-kernel relevance vector machine and whale optimization algorithm for lithium-ion battery. <i>Transactions of the Institute of Measurement and Control</i> , <b>2020</b> , 014233122110420	1.8	3
227	A Prognostics and Health Management for Information and Electronics-Rich Systems <b>2012</b> , 19-30		3
226	A Review of Second-Life Lithium-Ion Batteries for Stationary Energy Storage Applications. <i>Proceedings of the IEEE</i> , <b>2022</b> , 110, 735-753	14.3	3
225	Online Degradation State Assessment Methodology for Multi-Mode Failures of Insulated Gate Bipolar Transistor. <i>IEEE Access</i> , <b>2020</b> , 8, 69471-69481	3.5	2
224	Fault Diagnostics and Lifetime Prognostics for Phosphor-Converted White LED Packages. <i>Solid State Lighting Technology and Application Series</i> , <b>2018</b> , 255-299	0.7	2
223	Introduction to PHM <b>2018</b> , 1-37		2
222	PHM of Li-ion Batteries <b>2018</b> , 349-375		2
221	System-Level Fault Prognosis for High-Speed Railway On-Board Systems. <i>Transportation Research Record</i> , <b>2019</b> , 2673, 584-595	1.7	2
220	Perceptual Vibration Hashing by Sub-Band Coding: An Edge Computing Method for Condition Monitoring. <i>IEEE Access</i> , <b>2019</b> , 7, 129644-129658	3.5	2
219	Considerations in implementing canary based prognostics <b>2015</b> ,		2
218	Comparative Study of Metal Films and Their Affinity for Metal Whisker Growth. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2012</b> , 2, 739-747	1.7	2
217	Comparison of statistical models for the lumen lifetime distribution of high power white LEDs <b>2012</b> ,		2
216	Health assessment of electronic systems <b>2013</b> ,		2
215	A comparative review of prognostics-based reliability methods for Lithium batteries <b>2011</b> ,		2

214	Reliability assessment of immersion silver finished circuit board assemblies using clay tests <b>2009</b> ,		2
213	Characterization of Encapsulant Properties <b>2009</b> , 181-224		2
212	. <i>IEEE Transactions on Reliability</i> , <b>2009</b> , 58, 264-270	4.6	2
211	An investigation into fan reliability <b>2012</b> ,		2
210	Cell balancing technology in battery packs <b>2012</b> ,		2
209	Detection of solder joint failure precursors on tin-lead and lead-free assemblies using RF impedance analysis <b>2009</b> ,		2
208	Application of FPGA units in combined temperature cycle and vibration reliability tests of lead-free interconnections <b>2008</b> ,		2
207	<b>2008</b> ,		2
206	Failure site isolation on passive RFID tags <b>2008</b> ,		2
205	Reliability Assessment on Insertion Mount Assembly under Vibration Conditions <b>2007</b> ,		2
204	Assessment of long-term reliability in lead-free assemblies		2
203	The story behind the red phosphorus mold compound device failures <b>2005</b> ,		2
202	Lead-free Electronics: Overview <b>2006</b> , 1-44		2
201	Open trace defects in FR4 printed circuit boards. <i>Circuit World</i> , <b>2006</b> , 32, 3-7	0.7	2
200	Assessing lead-free intellectual property. <i>Circuit World</i> , <b>2004</b> , 30, 46-51	0.7	2
199	The role of the U.S National Highway Traffic Safety Administration in automotive electronics reliability and safety assessment. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2005</b> , 28, 571-580		2
198	Effect of corrosion on the transfer impedance of zinc-coated steel enclosures. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2000</b> , 42, 71-76	2	2
197	Characterization of a non-woven randomly dispersed short fiber laminate. <i>Circuit World</i> , <b>1998</b> , 24, 34-37	0.7	2

196	Placement design for producibility. <i>Journal of Electronics Manufacturing</i> , <b>1991</b> , 01, 61-76		2
195	. <i>IEEE Aerospace and Electronic Systems Magazine</i> , <b>1992</b> , 7, 16-19	2.4	2
194	. <i>IEEE Transactions on Components, Hybrids and Manufacturing Technology</i> , <b>1992</b> , 15, 542-552		2
193	A Zonal Decomposition Methodology for Detailed Temperature Field Evaluation. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , <b>1990</b> , 112, 260-266	2	2
192	BGA Solder Life Prediction under Combined Power and Temperature Cycling Condition. <i>International Symposium on Microelectronics</i> , <b>2012</b> , 2012, 000531-000534	0.2	2
191	Effect of ENEPIG Surface Finish on the Vibration Reliability of Solder Interconnects. <i>International Symposium on Microelectronics</i> , <b>2013</b> , 2013, 000115-000119	0.2	2
190	. <i>IEEE Access</i> , <b>2021</b> , 9, 144726-144739	3.5	2
189	Temperature as a Reliability Factor <b>1997</b> , 27-41		2
188	Detection and detectability of intermittent faults based on moving average T2 control charts with multiple window lengths. <i>Journal of Process Control</i> , <b>2020</b> , 92, 296-309	3.9	2
187	Assembly Options and Challenges for Electronic Products With Lead-Free Exemption. <i>IEEE Access</i> , <b>2020</b> , 8, 134194-134208	3.5	2
186	Translation Invariance-Based Deep Learning for Rotating Machinery Diagnosis. <i>Shock and Vibration</i> , <b>2020</b> , 2020, 1-16	1.1	2
185	Electronic Circuit Diagnosis with No Data <b>2019</b> ,		2
184	Plastic encapsulant materials <b>2019</b> , 47-121		2
183	. <i>IEEE Access</i> , <b>2021</b> , 9, 89527-89532	3.5	2
182	Performance Degradation of Hydraulic Vehicle Dampers <b>2018</b> ,		2
181	Failure Modes, Mechanisms, Effects, and Criticality Analysis of Ceramic Anodes of Solid Oxide Fuel Cells. <i>Electronics (Switzerland)</i> , <b>2018</b> , 7, 323	2.6	2
180	Effects of Moisture and Temperature on Membrane Switches in Laptop Keyboards. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2018</b> , 18, 535-545	1.6	2
179	Machine Learning: Diagnostics and Prognostics <b>2018</b> , 163-191		2

178	Development of an Informative Lithium-Ion Battery Datasheet. <i>Energies</i> , <b>2021</b> , 14, 5434	3.1	2
177	. <i>IEEE Access</i> , <b>2021</b> , 1-1	3.5	2
176	Mahalanobis Distance Approach for Insulated Gate Bipolar Transistors Diagnostics. <i>Advanced Concurrent Engineering</i> , <b>2010</b> , 643-651		2
175	Plastic Packaging <b>1997</b> , 394-508		2
174	A machine learning-based framework for online prediction of battery ageing trajectory and lifetime using histogram data. <i>Journal of Power Sources</i> , <b>2022</b> , 526, 231110	8.9	2
173	The Distribution and Detection Issues of Counterfeit Lithium-Ion Batteries. <i>Energies</i> , <b>2022</b> , 15, 3798	3.1	2
172	Effect of different lubricant films on contact resistance of stationary separable gold-plated electrical contacts. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2019</b> , 30, 14368-14381	2.1	1
171	A Comparative Study of Deep Learning-Based Diagnostics for Automotive Safety Components Using a Raspberry Pi <b>2019</b> ,		1
170	Effect of metal foams on the dynamic response time of a magnetorheological damper. <i>International Journal of Applied Electromagnetics and Mechanics</i> , <b>2019</b> , 61, 185-199	0.4	1
169	Degradation Monitoring of Insulation Systems Used in Low-Voltage Electromagnetic Coils under Thermal Loading Conditions from a Creep Point of View. <i>Sensors</i> , <b>2020</b> , 20,	3.8	1
168	Electromagnetic coil equivalent circuit model sensitivity analysis for impedance-based insulation health monitoring <b>2017</b> ,		1
167	Prognostics and Health Management. <i>Springer Series in Reliability Engineering</i> , <b>2018</b> , 447-507	0.2	1
166	Economic design of the mean prognostic distance for canary-equipped electronic systems. <i>Microelectronics Reliability</i> , <b>2012</b> , 52, 1086-1091	1.2	1
165	Incremental learning approach for improved prediction <b>2013</b> ,		1
164	Prognostics of lithium-ion batteries using a deterministic Bayesian approach <b>2015</b> ,		1
163	A prognostics and health management method for instrumentation system remanufacturing <b>2015</b> ,		1
162	Introduction to LED Thermal Management and Reliability. <i>Solid State Lighting Technology and Application Series</i> , <b>2014</b> , 3-14	0.7	1
161	Scintillation Conditioning of Tantalum Capacitors With Manganese Dioxide Cathodes. <i>IEEE Transactions on Device and Materials Reliability</i> , <b>2014</b> , 14, 630-638	1.6	1

160	Prognostics and health management based refurbishment for life extension of electronic systems <b>2014,</b>	1
159	State of charge estimation for electric vehicle batteries under an adaptive filtering framework <b>2012,</b>	1
158	Health monitoring based liability <b>2012,</b>	1
157	Ductile-to-brittle transition of flip-chip solder joints influenced by electromigration <b>2010,</b>	1
156	Research on electrostatic monitoring technology for aero-engine gas path <b>2010,</b>	1
155	Symbolic time series analysis based health condition forecasting in complex electronic systems <b>2010,</b>	1
154	Improving computer manufacturing management through Lean Six Sigma and PHM <b>2010,</b>	1
153	Degradation of digital signal characteristics due to intermediate stages of interconnect failure <b>2010,</b>	1
152	Impact of thermal aging on the thermal fatigue durability of Pb-free solder joints <b>2010,</b>	1
151	Rolling element bearing fault detection: Combining energy operator demodulation and wavelet packet transform <b>2011,</b>	1
150	Failure modes, mechanisms, and effects analysis for LED backlight systems used in LCD TVs <b>2011,</b>	1
149	A theoretical model to minimize the operational cost for canary-equipped electronic system's health management <b>2011,</b>	1
148	Physics-of-failure analysis of cooling fans <b>2011,</b>	1
147	A residual estimation based approach for isolating faulty parameters <b>2009,</b>	1
146	A fusion approach for anomaly detection in hard disk drives <b>2012,</b>	1
145	The Role of Aging on Dynamic Failure Envelopes of OSP-Sn37Pb Interconnects in Plastic Ball Grid Array (PBGA) Packages. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2009</b> , 32, 173-179	1
144	Effect of lead-free soldering on key material properties of FR-4 printed circuit board laminates <b>2008,</b>	1
143	Anomaly detection in electronic products <b>2008,</b>	1

142	Low temperature electrical measurements of silicon bipolar monolithic microwave integrated circuit (MMIC) amplifiers. <i>Microelectronics Reliability</i> , <b>2006</b> , 46, 326-334	1.2	1
141	Thermal Performance Measurements of Thermal Interface Materials Using the Laser Flash Method <b>2007</b> , 405		1
140	Lead-free Legislations, Exemptions, and Compliance <b>2006</b> , 45-79		1
139	Tin Whiskers in Electronics <b>2006</b> , 551-625		1
138	Recommendations for Future Avionics Hardware Development <b>2002</b> ,		1
137	Parts Selection and Management to Avoid Counterfeit Electronic Parts <b>2005</b> , 127-137		1
136	Upgrading of a single inline memory module. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>2002</b> , 25, 266-269		1
135	Thermal characteristics of glass-metal composition plasma display panels. <i>IEEE Transactions on Advanced Packaging</i> , <b>2002</b> , 25, 488-494		1
134	Flat panel displays ¶what is going on in East Asia outside Japan. <i>Circuit World</i> , <b>1998</b> , 24, 20-27	0.7	1
133	Open Forum: Editorial: Virtual product development. <i>IEEE Transactions on Components and Packaging Technologies</i> , <b>1998</b> , 21, 610-610		1
132	Experimental Evaluation of Mechanical Behavior of GaAs Wafer Material. <i>Materials Research Society Symposia Proceedings</i> , <b>1991</b> , 226, 141		1
131	A Coupled Algorithmic-Heuristic Approach for Design Optimization. <i>IEEE Transactions on Systems, Man, and Cybernetics</i> , <b>1987</b> , 17, 289-293		1
130	OPTIMIZED REDUNDANCY ALLOCATION FOR ELECTRONIC EQUIPMENT. <i>Engineering Optimization</i> , <b>1988</b> , 14, 101-114	2	1
129	Dynamic Equivalent Circuit Model to Estimate State-Of-Health Of Lithium-Ion Batteries. <i>IEEE Access</i> , <b>2022</b> , 1-1	3.5	1
128	Reduction of Skin Stretch Induced Motion Artifacts in Electrocardiogram Monitoring Using Adaptive Filtering		1
127	Prognostics and Health Assessment Implementation for Electronic Products. <i>Journal of the IEST</i> , <b>2010</b> , 53, 44-58	0.2	1
126	Prognostics and Health Monitoring of Electronics <b>2008</b> , 1107-1122		1
125	Thermal Cycling Reliability of Alternative Low-Silver Tin-based Solders. <i>International Symposium on Microelectronics</i> , <b>2013</b> , 2013, 000120-000127	0.2	1

124	Failure Analysis of Assemblies and Devices <b>2001</b> , 338-369		1
123	Mechanics of Wirebond Interconnects <b>1993</b> , 729-802		1
122	Data Center Energy Flow and Efficiency <b>2014</b> , 9-30		1
121	Experimental Approach to Determine Damage Curves for SnAgCu Solder Under Sequential Cyclic Loads. <i>Journal of Electronic Materials</i> , <b>2020</b> , 49, 1412-1420	1.9	1
120	Experimental verification of lithium-ion battery prognostics based on an interacting multiple model particle filter. <i>Transactions of the Institute of Measurement and Control</i> , <b>2020</b> , 014233122096157	1.8	1
119	The Use of UL 1642 Impact Testing for Li-ion Pouch Cells. <i>IEEE Access</i> , <b>2019</b> , 7, 176706-176711	3.5	1
118	Electrostatic Charging of a Human Body Caused by Activities and Material Combinations in Hospitals. <i>IEEE Transactions on Electromagnetic Compatibility</i> , <b>2020</b> , 62, 315-323	2	1
117	Sparse Reconstruction for Microdefect Detection of Two-Dimensional Ultrasound Image Based on Blind Estimation. <i>IEEE Transactions on Industrial Electronics</i> , <b>2021</b> , 68, 10154-10161	8.9	1
116	. <i>IEEE Access</i> , <b>2021</b> , 1-1	3.5	1
115	Analysis and experiments on transmission characteristics of LCCL mobile wireless power transfer system. <i>IEICE Electronics Express</i> , <b>2018</b> , 15, 20180964-20180964	0.5	1
114	Health and Remaining Useful Life Estimation of Electronic Circuits <b>2018</b> , 279-327		1
113	A mathematical method for open-circuit potential curve acquisition for lithium-ion batteries. <i>Journal of Electroanalytical Chemistry</i> , <b>2021</b> , 895, 115488	4.1	1
112	Decoupling the thermal and non-thermal effects of discharge C-rate on the capacity fade of lithium-ion batteries. <i>Journal of Power Sources</i> , <b>2021</b> , 510, 230390	8.9	1
111	Physics-of-Failure based Reliability Engineering 389-402		1
110	Standards Relating to Data Center <b>2014</b> , 31-45		1
109	Part Risk Assessment and Mitigation <b>2014</b> , 95-114		1
108	Wire Bond Pads <b>2014</b> , 111-131		1
107	Field Reliability Estimation for Cochlear Implants. <i>IEEE Transactions on Biomedical Engineering</i> , <b>2015</b> , 62, 2062-9	5	0

106	Managing Electronics Part Changes in the Supply Chain. <i>IEEE Transactions on Components, Packaging and Manufacturing Technology</i> , <b>2018</b> , 8, 883-895	1.7	○
105	Rapid Assessment Testing of Polymer Aluminum Electrolytic Capacitors in Elevated Temperature/Humidity Environments. <i>Journal of Failure Analysis and Prevention</i> , <b>2016</b> , 16, 1059-1066	0.9	○
104	Long-Term Non-Operating Reliability of Electronic Products. <i>Journal of Electronic Packaging, Transactions of the ASME</i> , <b>1997</b> , 119, 145-146	2	○
103	Use of high temperature operating life data to mitigate risks in long-duration space applications that deploy commercial-grade plastic encapsulated semiconductor devices. <i>Microelectronics Reliability</i> , <b>2006</b> , 46, 360-366	1.2	○
102	Methods for Predicting the Remaining Life of Electronic Assemblies With Carbon Nanotubes and an Optical Transduction Technique <b>2003</b> , 407		○
101	Failure Modes and Mechanisms <b>2004</b> , 138-157		○
100	Learnable Wavelet Scattering Networks: Applications to Fault Diagnosis of Analog Circuits and Rotating Machinery. <i>Electronics (Switzerland)</i> , <b>2022</b> , 11, 451	2.6	○
99	Signal Connector Selection <b>2020</b> , 251-260		○
98	The Problem of PHM Cloud Cluster in the Context of Development of Self-maintenance and Self-recovery Engineering Systems. <i>Lecture Notes in Mechanical Engineering</i> , <b>2015</b> , 1509-1520	0.4	○
97	Environmental Scanning Electron Microscopic Investigation of Interfacial Defects in Electronic Packages <b>1994</b> , 461-468		○
96	Bonding Metallurgies <b>2014</b> , 39-56		○
95	Reliability modeling for multistage systems subject to competing failure processes. <i>Quality and Reliability Engineering International</i> , <b>2021</b> , 37, 2936-2949	2.6	○
94	Construction of a deep sparse filtering network for rotating machinery fault diagnosis. <i>Proceedings of the Institution of Mechanical Engineers, Part D: Journal of Automobile Engineering</i> , 095440702110148	1.4	○
93	Nonparametric Model-Based Online Junction Temperature and State-of-Health Estimation for Insulated Gate Bipolar Transistors. <i>IEEE Access</i> , <b>2021</b> , 9, 95304-95316	3.5	○
92	Effects of external pressure on phase stability and diffusion rate in lithium-ion cells. <i>Journal of Electroanalytical Chemistry</i> , <b>2021</b> , 895, 115400	4.1	○
91	A novel approach for flip chip inspection based on improved SDELM and vibration signals. <i>Science China Technological Sciences</i> , 1	3.5	○
90	Breaking the Trust: How Companies Are Failing Their Customers. <i>IEEE Access</i> , <b>2019</b> , 7, 52522-52531	3.5	
89	Development of a cycle counting algorithm with temporal parameters. <i>Microelectronics Reliability</i> , <b>2020</b> , 109, 113652	1.2	

- 88 Life Prediction. *Springer Series in Reliability Engineering*, **2018**, 115-139 0.2
- 87 Physics-of-Failure Approach for Electronics. *Springer Series in Reliability Engineering*, **2018**, 417-445 0.2
- 86 PHM in Healthcare **2018**, 431-449
- 85 Analysis of PHM Patents for Electronics **2018**, 613-647
- 84 Physics-of-Failure Approach to PHM **2018**, 61-84
- 83 Sensor Systems for PHM **2018**, 39-60
- 82 Transmission characteristics analysis of an MCR-WPT system with SP resonance structure based on harmonic current influence. *IEICE Electronics Express*, **2019**, 16, 20190460-20190460 0.5
- 81 ENERGY EFFICIENCY AND RELIABILITY RISK MITIGATION OF DATA CENTERS THROUGH PROGNOSTICS AND HEALTH MANAGEMENT. *WSPC Series in Advanced Integration and Packaging*, **2014**, 357-375
- 80 ARINC Specification 653, Avionics Application Software Standard Interface **2017**, 624-631
- 79 Energy Efficiency and Reliability Risk Mitigation of Data Centers Through Prognostics and Health Management **2014**, 311-327
- 78 Energy Efficiency and Reliability Risk Mitigation of Data Centers Through Prognostics and Health Management **2014**, 311-327
- 77 Counterfeit capacitors in the supply chain. *Journal of Materials Science: Materials in Electronics*, **2014**, 25, 645-652 2.1
- 76 The electronics counterfeiting problem. *Circuit World*, **2012**, 38, 163-168 0.7
- 75 Failure Causes of a Polymer Resettable Circuit Protection Device. *Journal of Electronic Materials*, **2012**, 41, 2419-2430 1.9
- 74 . *IEEE Design and Test of Computers*, **2011**, 28, 58-65
- 73 Editorial - Science, Technology, and Industrial Policy. *IEEE Transactions on Components and Packaging Technologies*, **2010**, 33, 836-839
- 72 Defect and Failure Analysis Techniques for Encapsulated Microelectronics **2009**, 287-350
- 71 Qualification and Quality Assurance **2009**, 351-415

- 70 Electromigration in flip-chip solder joints **2011**, 285-329
- 69 Encapsulation Defects and Failures **2009**, 225-285
- 68 China as Hegemon of the Global Electronics Industry: How It Got That Way and Why It Won't Change. *IEEE Transactions on Components and Packaging Technologies*, **2009**, 32, 935-939
- 67 Plastic Encapsulated Microelectronics; Materials, Processes, Quality, Reliability, and Application. *Journal of Electronic Packaging, Transactions of the ASME*, **1997**, 119, 144-145 2
- 66 Quality Conformance and Qualification of Microelectronic Packages and Interconnects. *Journal of Electronic Packaging, Transactions of the ASME*, **1997**, 119, 78-78 2
- 65 Open Forum: Editorial. *IEEE Transactions on Components and Packaging Technologies*, **2008**, 31, 229-229
- 64 Component-level Issues in Lead-free Electronics **2006**, 507-549
- 63 Lead-free Technologies in the Japanese Electronics Industry **2006**, 697-724
- 62 Guidelines for Implementing Lead-free Electronics **2006**, 725-758
- 61 Costs to Lead-free Migration **2006**, 683-696
- 60 Lead-free Separable Contacts and Connectors **2006**, 627-661
- 59 Coupled Thermal-Stress Analysis for FC-BGA Packaging Reliability Design **2006**, 289
- 58 Manufacturer Assessment Procedure and Criteria **2005**, 63-72
- 57 Part Assessment Guidelines and Criteria **2005**, 73-95
- 56 Tracking Part Changes Through the Part Supply Chain **2005**, 109-125
- 55 Determination of the Life Cycle Environment **2005**, 145-170
- 54 Reliability Assessment **2005**, 191-202
- 53 Open Forum Editorial. *IEEE Transactions on Components and Packaging Technologies*, **2005**, 28, 371-371

- 52 . *IEEE Transactions on Components and Packaging Technologies*, **2005**, 28, 549-554
- 51 Product Reliability, Maintainability, and Supportability Handbook. *Journal of Electronic Packaging, Transactions of the ASME*, **1996**, 118, 188-189 2
- 50 Interfacial Debonding in PWBs. *Materials Research Society Symposia Proceedings*, **1993**, 323, 371
- 49 Handbook of Electronic Packaging Design. *Journal of Electronic Packaging, Transactions of the ASME*, **1992**, 114, 365-365 2
- 48 Approximating the Steiner Tree in the Placement Process. *Journal of Electronic Packaging, Transactions of the ASME*, **1989**, 111, 228-235 2
- 47 Pressure Gradient method for solving incompressible Navier-Stokes equations with curvilinear coordinate system. *Mathematical and Computer Modelling*, **1990**, 14, 732-736
- 46 KNOWLEDGE GATHERING FOR HEURISTIC PROGRAMMING IN DESIGN OPTIMIZATION. *Engineering Optimization*, **1987**, 11, 317-326 2
- 45 What Research Is Underway to Advance R&M Automation for Electronics? Presentation and Workshop Discussion. *IEEE Transactions on Reliability*, **1987**, R-36, 516-522 4.6
- 44 Electronic Hardware Reliability. *The Electrical Engineering Handbook*, **2007**, 20-1-20-24
- 43 Connector Housing **2020**, 17-30
- 42 Advanced Technology Attachment Connectors **2020**, 261-274
- 41 Fretting in Connectors **2020**, 147-172
- 40 Examples of Connectors **2020**, 313-329
- 39 Power Connectors **2020**, 275-288
- 38 What Is an Electrical Connector? **2020**, 1-15
- 37 Contact Plating **2020**, 43-65
- 36 Contact Interface **2020**, 75-88
- 35 The Back-End Connection **2020**, 89-101

34 Appendix A Standards **2020**, 331-345

33 Contact Spring **2020**, 31-42

32 Selecting the Right Connector **2020**, 207-249

31 Supplier Selection **2020**, 197-205

30 Loads and Failure Mechanisms **2020**, 103-145

29 Insertion and Extraction Forces **2020**, 67-74

28 Applications of Sensor Systems in Prognostics and Health Management **2017**, 377-392

27 Design for Reliability **2009**, 201-217

26 Confidence Intervals **2009**, 83-94

25 Process Capability and Process Control **2009**, 421-445

24 Failure Modes, Mechanisms, and Effects Analysis **2009**, 185-200

23 System Reliability Modeling **2009**, 219-238

22 Solder Joint Reliability of SnBi Finished TSOPs with Alloy 42 Lead-Frame under Temperature Cycling. *Journal of ASTM International*, **2010**, 7, 102939

21 A Prognostics and Health Management for Information and Electronics-Rich Systems. *Journal of Japan Institute of Electronics Packaging*, **2010**, 13, 484-492

O.1

20 Wire Bond Evaluation **2014**, 57-71

19 Thermal Reliability Tests **2014**, 73-91

18 Concerns and Solutions **2014**, 133-149

17 Humidity and Electromigration Tests **2014**, 93-109

- 16 Part Reliability Assessment in Data Centers **2014**, 115-139
- 15 Reliability Risks Under Free Air Cooling **2014**, 71-93
- 14 Life Cycle Risk Mitigations **2014**, 141-158
- 13 Electrical Connectors for Underwater Applications **2020**, 289-311
- 12 Early fault detection of gas turbine hot components under different ambient and operating conditions. *Proceedings of the Institution of Mechanical Engineers, Part G: Journal of Aerospace Engineering*, 095441002098689 0.9
- 11 Position and enforcement practice of the People's Republic of China's pharmaceutical data exclusivity protection. *Drug Design, Development and Therapy*, **2016**, 10, 2015-20 4.4
- 10 ACA Curing Process Optimization Based on Curing Degree Considering Shear Strength of Joints. *IEEE Access*, **2019**, 7, 182906-182915 3.5
- 9 Qualification and quality assurance **2019**, 375-429
- 8 An Editorial From the Editor-in-Chief of the IEEE ACCESS, at the End of his Six Year Term. *IEEE Access*, **2018**, 6, 72046-72046 3.5
- 7 A PHM Roadmap for Electronics-Rich Systems **2018**, 649-689
- 6 PHM-Based Qualification of Electronics **2018**, 329-348
- 5 PHM of Light-Emitting Diodes **2018**, 377-430
- 4 The Role of PHM at Commercial Airlines **2018**, 503-534
- 3 eMaintenance **2018**, 559-587
- 2 Comparison between Synthetic Oil Lubricants for Reducing Fretting Degradation in Lightly Loaded Gold-Plated Contacts. *IEEE Transactions on Components, Packaging and Manufacturing Technology*, **2022**, 1-1 1.7
- 1 Lithium-ion battery strain gauge monitoring and depth of discharge estimation. *Journal of Electrochemical Energy Conversion and Storage*, 1-18 2